

PAH8002EP: Low Power Optical Heart Rate Detection Sensor

General Description

The PAH8002EP is a low power and high-performance CMOS-process optical sensor with three LEDs: two Green and one Infrared, and integrated DSP, targeted as a Heart Rate Detection (HRD) sensor. It is based on optical sensing technology that captures higher resolution image than the traditional photodiode. The images are then processed through our integrated DSP to attain processed PPG (Photoplethysmogram) data for use in deducing heart rate.

Key Features

- Heart rate detection function (HRD)
- SRAM buffer support
- Integrated ultra-low power mode, while in Sleep mode
- Adjustable sleep rate control
- Communication interface options
 - I²C
 - Four-Wire SPI
- I²C interface up to 1 Mbit/s
- SPI interface up to 2 Mbit/s
- Hardware reset support
- Integrated chip-on-board LEDs with wavelength of 525nm and 940nm

Applications

- Heart Rate Monitor Accessories
- Wearables: Smartwatch, Wrist Band

Key Parameters

Parameter	Value
Operating Temperature,	-20 to +60
_Tj (°C)	
Array Size	1 pixel
Pixel Size (μm)	780 x 780
Max Frame Rate (fps)	50K
Dynamic Range (dB)	70
Supply Voltage (V)	VDDM: 3.3 – 3.6
	VDD_LEDx: 3.3 – 3.6
	VDDIO: 1.62 – 3.6
	Analog: 2.8
	Digital: 1.8
Power Consumption	Active:
(mW) @3.3V	4.95 with one LED
Note: Including LED	8.25 with two LEDs
current, without I/O	0.165 with IR Touch
toggling, package only	Detection
	Sleep: 0.08
Heart Rate Measurement Range (bpm)	30 - 240
Package Size (mm)	3.6 x 6.36 x 1.0

Ordering Information

Part Number	Package Type				
PAH8002EP-IP	22-Pin LGA				





For any additional inquiries, please contact us at http://www.pixart.com/contact.asp

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1.0 Introduction

1.1 Overview

The PAH8002EP is a low power and high-performance CMOS-process optical sensor, targeted as a Heart Rate Detection (HRD) sensor. It is built-in with 2 Green LEDs, 1 Infrared LED and integrated DSP It comes with two communication interfaces, which are I²C supporting up to 1 Mbit/s and Four-Wire SPI supporting up to 2 Mbit/s. SRAM buffer of 832 bytes is supported for the power saving at the host.

The Figure 1 shows the architecture block diagram of the device. Refer to the subsequent chapters for detailed information on the functionality of the different interface blocks.

Note: Throughout this document PAH8002EP low power Optical CMOS Heart Rate Sensor is referred to as the sensor.

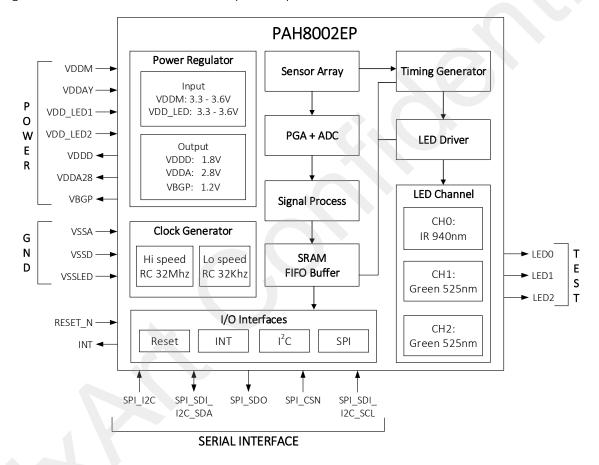


Figure 1. Functional Block Diagram

1.2 Terminology

Term	Description
GND	Ground
BiDir	Bi-Directional
PPG	Photoplethysmogram
Touch	Touch detection for wear on or wear off
SW reset	Software reset by register

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1.3 Signal Description

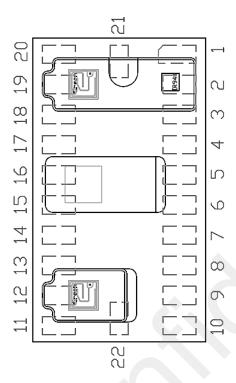


Figure 2. Pin Configuration

Table 1. Signal Pins Description

Pin No.	Signal Name	Type	Description		
Function	al Group:	Power Supp	olies		
1	VDD_LED01	Input	R/Green LED Anode. Provide VDDM supply voltage		
2	VDDAY	Input	Analog circuit power regulator input. Connect to VDDA28 or provide 2.8V voltage		
3	VDDA28	Output	Analog circuit power regulator output. Must connect 1µF capacitor to GND		
4	VDDD	Output	Digital circuit power regulator output. Must connect 1µF capacitor to GND		
5	VBGP	Output	Reference regulator output. Must connect 0.1µF capacitor to GND		
7	VDDM	Input	Power supply (3.3 - 3.6V) for internal power regulator		
8	VSSLED	GND	LED Ground		
15	VSSD	GND	Digital Ground		
19	VDDIO	Input	I/O Power Supply (1.62 - 3.6V)		
20	VSSA	GND	Analog Ground		
22	VDD_LED2	Input	Green LED Anode. Provide VDDM supply voltage		
Function	al Group:	Interface			
11	SPI SDI 12C SDA	BiDir	4-wire SPI: Data input		
	311_3D1_12C_3D11	DIDII	l ² C: Data input-output		
12	SPI_SDO	Output	4-wire SPI: Data output		
13	SPI_CSN	Input	4-wire SPI: Chip Select. Active Low		
14	SPI_SCLK_I2C_SCL	Input	4-wire SPI/ I ² C: Clock		

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Pin No.	Signal Name	Туре	Description		
Functional Group: Functional I/O			/0		
16	INT	Output	Data ready interrupt. Default is edge sensitive interrupt, can be changed to level sensitive interrupt (high active) in INT_Type register		
17	SPI_I2C	Input	Interface Selection I ² C: Pull down (Tie to GND) 4-wire SPI: Pull high (Tie to VDDIO)		
18	RESET_N	Input	Hardware control to enter Reset Mode. Connect to VDDIO when not used Level High: Leave Reset Mode Level Low: Enter Reset Mode		
Function	al Group:	Reserved			
9	LED0	RSV	Reserved for LED0 test pin		
6	LED1	RSV	Reserved for LED1 test pin		
10	LED2	RSV	Reserved for LED2 test pin		
21	NC	RSV	Reserved. No Connection		

1.4 Sensor Array

1.4.1 Array Size

Table 2. Array Information

Description	Symbol	Min.	Тур.	Max.	Unit	Notes	
X Dimension	Χ		780		μm	No optical filter	
Y Dimension	Υ		780		μm		
Pixel Size	Pix		1 x 1		pixel		

1.4.2 Against Ambient Light

Support HW background subtraction to reduce ambient light interference. PAH8002 can detect background brightness and subtract this background value. Refer to 10.2.2 and 10.3.2 registers section.

1.4.3 Conversion Gain

Support two types of sensitivity levels: 1x and 4x to improve the performance on different human skin colors and skin tones, for example on the darker skin tone. Digital circuit can control capacitor value to optimize Conversion Gain. Refer to 10.2.3 registers section.

1.5 ADC Normalized Mode

1.5.1 Normalized Mode

Write 0x00 to Bank0 Address 0x50 and 0x51 to enable normalized mode. Refer to 8.1 AEC section and 10.7, 10.13 registers section.

ADC Data = ((AEC Range * Sampling Number * 2^20) / (PGA Gain * LED DAC * Exposure Time)) >> Normalized_Right_Shift

1.5.2 Non-normalized Mode

Write 0x01 to Bank0 Address 0x50 and 0x51 is disable normalized mode. Refer to 8.1 AEC section and 10.7, 10.13 registers section.

ADC Data = ((AEC Range * Sampling Number)

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1.6 Power Saving Mechanism

The sensor will enter into Sleep mode at most of the operating duration for power saving purpose. The low power timer will control clock source to reduce power consumption at Sleep mode. The sensor will wake up by itself during setting period. If three LED channels are used, these channels will be repeating in this sequence: CH0->CH1->CH2->CH1->CH2. Every channel will turn on each LED sampling number of exposure for better signal noise ratio. The sensor will get some raw data and save them into SRAM FIFO. Then the sensor will enter sleep mode for power saving and to be woke up by internal timer. Refer to 10.5 and 10.6 registers section.

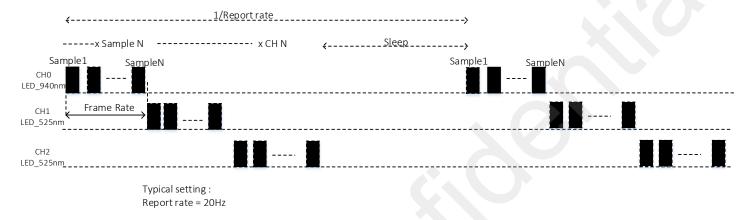


Figure 3. Three Channels LED Timing Diagram

2.0 Operating Specifications

2.1 Absolute Maximum Ratings

Table 3. Absolute Maximum Ratings

Parameters	Symbol	Min.	Max.	Unit	Notes
Analog Voltage	V_{DDM_MAX}	-0.4	$V_{DDM} + 0.3$	V	
I/O Voltage	$V_{\text{DDIO_MAX}}$	-0.4	$V_{DDIO} + 0.3$	V	
I/O Pin Input High Voltage	V_{DDIO_IN}	-0.4	V _{DDIO} + 0.3	V	All I/O pins
Relative Humidity	RH	0	50	%	Non-condensing, Non-biased
ESD	ESD _{HBM}		2	kV	Class 2 on all pins, as per human body model. JESD22-A114E with 15 sec zap interval.

Notes:

- 1. At room temperature.
- 2. Maximum Ratings are those values beyond which damage to the device may occur.
- 3. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability.
- 4. Functional operation under absolute maximum-rated conditions is not implied and should be restricted to the Recommended Operating Conditions.

2.2 Recommended Operating Conditions

Table 4. Recommended Operating Conditions

Description	Symbol	Min.	Тур.	Max.	Unit	Notes
Ambient Temperature	T _A	-20	25	60	°C	
Operating Junction Temperature	Tı	-20		60	°C	
Power Supply Voltage	V_{DDM}	3.25	3.3	3.6	V	Power regulator input supply. Includes ripples
Analog Supply Voltage	V_{DDAY}	2.66	2.8	2.94	V	If supply from external power regulator. Includes ripples
I/O Supply Voltage	$V_{\rm DDIO}$	1.62	1.8	3.6	V	Includes ripples
Power Regulator Output Voltage	V_{DDD}	1.62	1.8	1.98	V	For digital circuit. Includes ripples
	V _{DDA28}	2.52	2.8	3.08	V	For analog circuit to be connected to V _{DDAY} . Includes ripples
	V_{BGP}	1.08	1.2	1.32	V	For power regulator reference. Includes ripples
Supply Noise	V_{Npp}	-	-	100	mV_{p-p}	Peak to peak within 10K – 80 MHz
	SCK_SPI	-	-	2	MHz	
Serial Clock Frequency	SCK_I ² C	-	400 ¹	1000²	KHz	 Max value for Fast mode Max value for Fast mode plus

Note: PixArt does not guarantee the performance if the operating temperature is beyond the specified limit.

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2.3 Thermal Specifications

Table 5. Thermal Specifications

Parameters	Symbol	Min.	Тур.	Max.	Unit	Notes
Storage Temperature	Ts	-25	-	125	°C	
Lead-free Solder Temperature	T _P	-	-	245		Refer to Package Handling Information document

2.4 DC Characteristics

Table 6. DC Electrical Specifications

Parameters	Symbol	Min.	Typ.	Max.	Unit	Conditions
Peak Power Supply Current	I _{DDM_MAX}	-	-	100	mA	For V _{DDM}
reak rower supply current	I _{DDAY_MAX}	-	-	10	mΑ	For V _{DDAY}
Peak I/O Supply Current	I _{DDIO_MAX}	-	-	1	mA	For V _{DDIO}
Output Supply Current	I _{DDD_MAX}	-	-	80	mA	For V _{DDD}
Output Supply Current	I _{DDA28_MAX}	-	-	20	mA	For V _{DDA28}
Power Consumption						
Supply Current @ Sleep	IDDPD	-	25	75	uA	For sensor only Wakeup by read register
Inrush Current	I _{INRUSH}	-	-	60	mΑ	
With One Green LED						
Supply Current @ HRD PPG mode	I _{DDHRD}		1.2	3.0	mA	For sensor only, not including LED current, without I ² C interface I/O toggle
LED current	I _{DDLED}	-	0.3	-	mA	20 report/sec, LED DAC = 50mA, on yellow skin color
With Two Green LEDs						
Supply Current @ HRD PPG mode	Iddhrd	-	1.7	3.0	mA	For sensor only, not including LED current, without I ² C interface I/O toggle
LED current	IDDLED	-	0.8	-	mA	20 report/sec, LED DAC = 50mA, on yellow skin color
With IR Touch Detection						
Supply Current @ Touch Detection mode	IDDtouch		45		uA	For sensor only, not including LED current, without I ² C interface I/O toggle
LED current at touch	IDDLED	-	5	-	uA	3.8 report/sec, LED DAC = 50mA, on yellow skin color
1/0						
Input High Voltage	V _{IH}	0.7* V _{DDIO}	-	-	V	
Input Low Voltage	V _{IL}	-	-	0.3* V _{DDIO}	V	
Output High Voltage	V _{OH}	V _{DDIO} - 0.4	-	V _{DDIO} + 0.4	V	@I _{OH} = 2mA
Output Low Voltage	V _{OL}	-0.4	-	0.4	V	@I _{OL} = 2mA

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Parameters	Symbol	Min.	Тур.	Max.	Unit	Conditions
LED						
Sink current	I _{LED}	40	50	60	mA	@ LED DAC = 50mA
LED cathode voltage	V_{LED}	0.4		3.6	V	

Notes:

- 1. Electrical Characteristics are defined under recommended operating conditions.
- 2. All the parameters are tested under operating conditions: $V_{DDM} = 3.3V$, $V_{DDIO} = 1.8$ and 3.3V, $T_A = 25^{\circ}C$

2.5 AC Characteristics

Table 7. AC Electrical Specifications

Parameters	Symbol	Min.	Тур.	Max.	Unit	Conditions
Power Up from V _{DD} ↑	t _{PU}	200	300	400	ms	From V _{DD} ↑ to valid interface communication
SDI/SDO Read Hold Time	T _{HOLD}	-	3	-	us	Minimum hold time for valid data.
Address and data delay time	t _{delay}	2.75			us	Refer to Serial Interface section
Sensor Pulse Interrupt Width	t _{INT}	0.00625	0.5	16	us	Default 0.5us, can be changed in INT_Pulse_Width register
Rise and Fall Times: SDI/SDO	t _r , t _f	-	30	-	ns	C _L = 30 pF
HW Reset Time	t _{reset}	200	300	400	ms	Reset_N from low to high period

Notes:

- 1. Electrical Characteristics are defined under recommended operating conditions
- 2. All the parameters are tested under operating conditions: $T_A = 25$ °C, $V_{DDM} = 3.3$ V, $V_{DDIO} = 3.3$ V for 3.3V IO application and $V_{DDIO} = 1.8$ V for 1.8V IO application.

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3.0 Mechanical Specifications

3.1 Mechanical Dimension

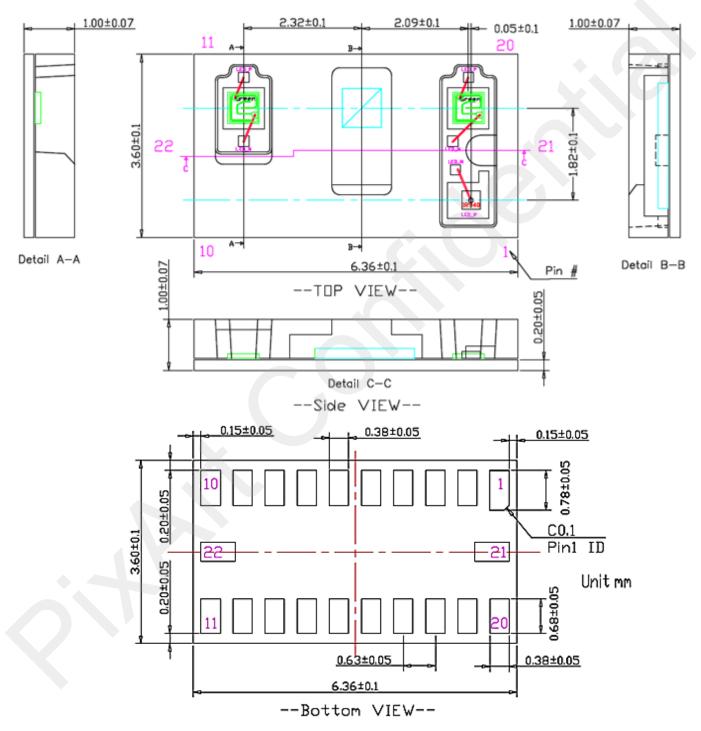


Figure 4. Package Outline Diagram

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3.2 Package Marking

Refer to Figure 5. Package marking for the code marking location on the device package.

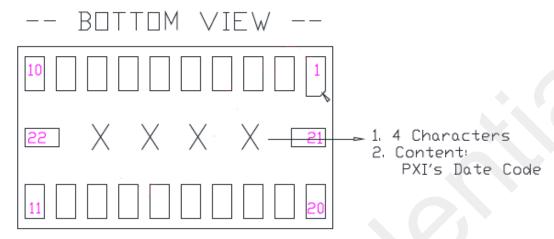


Figure 5. Package marking

Table 8. Code Identification

Marking	Description	
XXXX	PixArt Date Code	

4.0 System Level Description

4.1 System Overview

This section describes on how the sensor being used to make up a complete system including the explanation on the 3rd party components and how they work with the sensor.

The PAH8002 is based on CMOS image sensor technology. It is designed to meet the requirements as heart rate monitor accessories and wearables like smart watch or wrist band device. Figure 6 illustrates a system design for App Level diagram. The processor is accessing PPG data from 8002 sensor, then pass it to App level. APP level applies PixArt provided algorithm library to determine the heart rate data and waveform. Figure 7. System Design for Firmware Level illustrates a system design for Firmware Level diagram. The processor will also access PPG data from 8002 sensor, then perform heart rate calculation with PixArt algorithm library and send result to display or end device.

PAH8002 can be configured to generate different frame rate settings up to 50K fps.

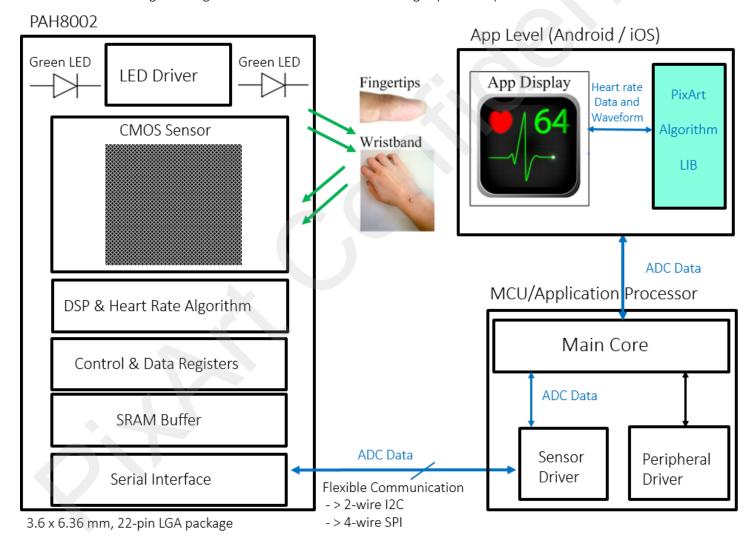


Figure 6. System Design for App Level

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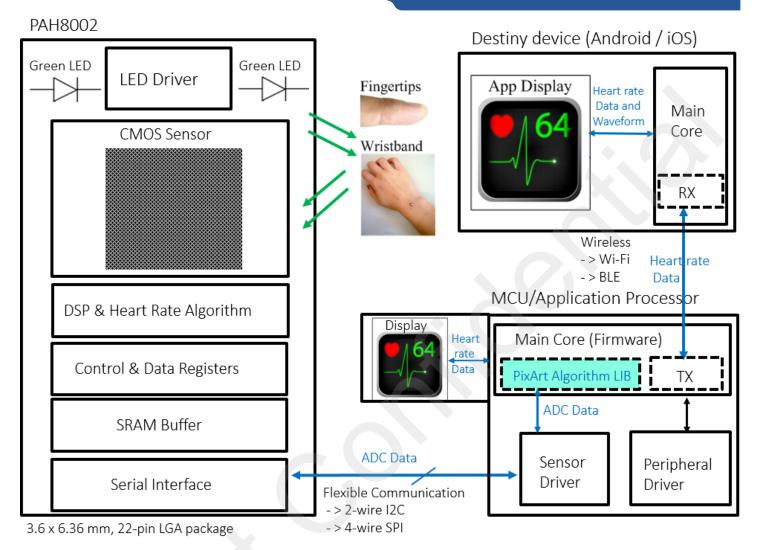


Figure 7. System Design for Firmware Level

4.2 Reference Schematic

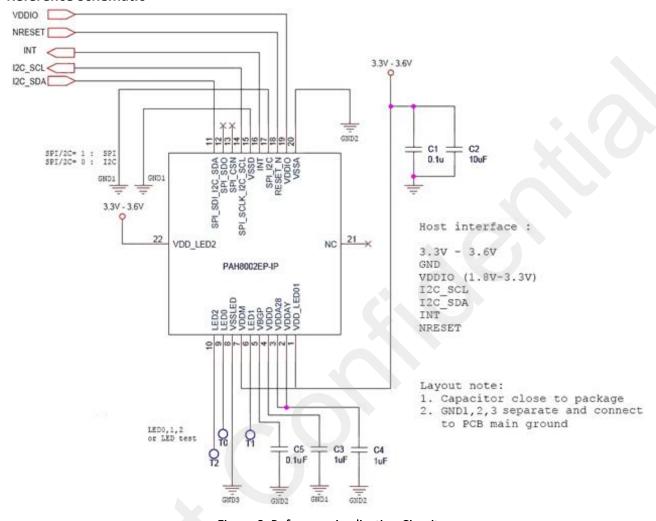


Figure 8. Reference Application Circuit

Design Guidelines 4.3

Schematic Design 4.3.1

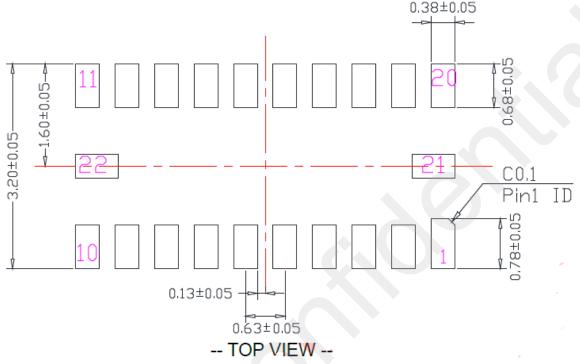
- 1. VDDM & VDDIO: 3.3V~3.6V (for 3.3V System)
- 2. VDDM: 3.3V~3.6V, VDDIO: 1.62V~1.98V (for 1.8V System)
- It is recommended to separate the power system for VDDM to avoid power interference.
- 4. SPI SDI 12C SDA and SPI SCLK 12C SCL pull high to VDDIO with resistor for I²C Only
- 5. VDDD, VDDA28 must have 1μF and VBGP must have 0.1μF capacitor connecting to GND and place closely to 8002.
- 6. The GND1, GND2 and GND3 must be separated and connected to PCB main GND.
- 7. INT pin is recommended to be connected to MCU HW INT as data ready INT for power saving.
- 8. Ensure that the VDDM and VDDIO's power noise should be under 100mV (with 0.1μF and 10μF capacitor)
- 9. Tie SPI 12C pin to VDDIO for SPI or tie to GND for I²C.
- 10. At power on, VDDM and VDDIO must be powered on at the same time or VDDIO to be powered on first before VDDM.
- 11. At power off, VDDM and VDDIO must be powered off at the same time or VDDM to be powered off first before VDDIO.

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4.3.2 PCB Layout Design

4.3.2.1 Recommend Layout PCB

Recommended Stencil Thickness: 0.1mm. PCB Layout can be refer to Figure 9. Recommend Layout PCB.



Notes: All dimension is mm.

Figure 9. Recommend Layout PCB

4.3.2.2 Recommended Stiffener type for FPC (Flex) back-side (at Sensor package area)

- 1. If use FPC (Flex) board, need add stiffener onto the back side to enhance the Flex strength.
- 2. Recommended Stiffener type: FR4 or stainless steel or equivalent material.

4.3.2.3 PCB Layout Guidelines

The following guidelines can be refer to Figure 10. PCB Layout Guide.

- 1. Capacitor 0.1μF and 1μF must be placed close to the sensor package.
- 2. The GND plane of GND of VSSA, VSSD and VSSLED must be layout separately and connected to the PCB's main GND.

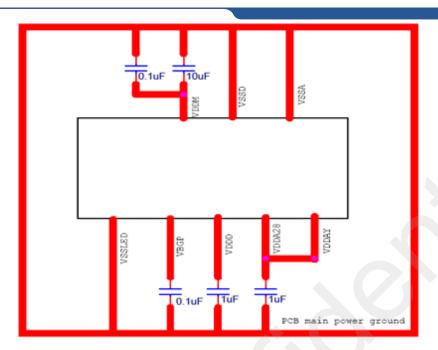


Figure 10. PCB Layout Guide

4.4 Recommend Guideline for PCB Assembly

Recommended vender and type for Pb-free solder paste

- 1. Almit LFM-48W TM-HP
- 2. Senju M705-GRN360-K

IR Reflow Soldering Profile can be refer to Figure 11. IR Reflow Soldering Profile:

Temperature profile is the most important control in reflow soldering. It must be fine-tuned to establish a robust process. The typical recommended IR reflow profile is:

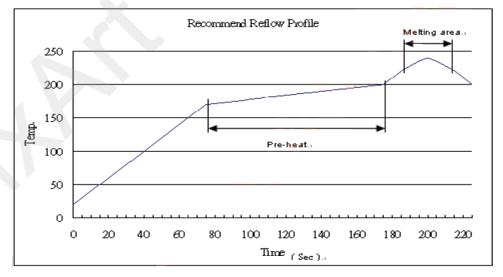


Figure 11. IR Reflow Soldering Profile

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Note:

(1) Average Ramp-up Rate (30°C to preheat zone): $1.5^2.5^{\circ}$ C/Sec

(2) Preheat zone:

(2.1) Temperature ramp from $170^{\sim}200^{\circ}$ C

(2.2) Exposure time: 90 +/- 30 sec

(3) Melting zone:

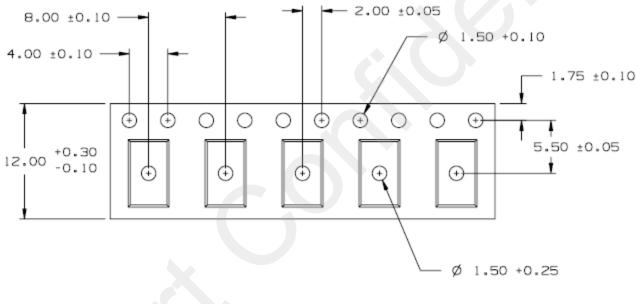
(3.1) Melting area temperature > 220° C for at least $30^{\sim}50$ sec

(3.2) Peak temperature: 245°C

MS Level: MS Level 3

4.5 Package Information

4.5.1 Carrier Tape Drawing



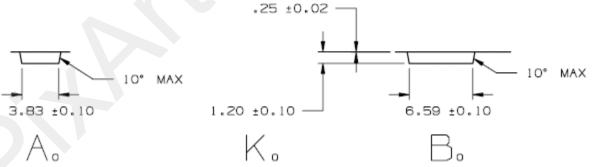


Figure 12. Carrier Tape Drawing

4.5.2 Unit Orientation

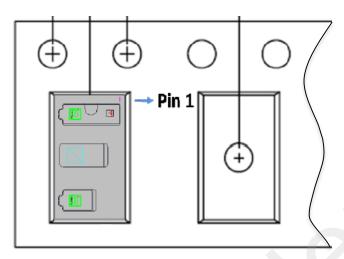


Figure 13. Unit Orientation

The maximum capacity of one packing box for PAH8002EP-IP: One Inner packing box = 2500 units Note: The Tape and Reel packing with vacuum pack is 1year storage available @ 25° C, 50%RH

5.0 Power States & Sequence

5.1 Power States

State	Functional Description
OFF	No power supply, all the voltage rails and clocks are gated.
RESET	This mode is entered when power-up sequence is executed and RESET_N is held low. The sensor stays in this state as long as RESET_N is held low. High on RESET_N will transition the sensor to Ready mode. After power up, when the sensor is waiting for RESET_N to go high, all the rails to the individual functional blocks shall be internally gated. Any time the RESET_N is pulled low the sensor shall enter this mode.
READY	The sensor is transitioned to this mode when RESET_N is set to high or SW reset by register. This mode can be thought of as a mode for re-initialization of the registers if they are different from the default register settings. All the rails and clocks are enabled. There is no capture or transmission of data on the SPI/I ² C lanes. All the functional blocks are enabled.
SLEEP ¹	This mode is entered from Ready mode either by using I ² C or SPI. When I ² C or SPI is used the user will transition by setting Sleep Sequence. The sensor stays in this mode until the user transitions back to PPG mode or Touch mode by read ID and write 0x00 to bank2 addr0x70, then SW reset and setting PPG initial setting or Touch initial setting.
PPG ²	This mode is obtaining Heart rate PPG raw data from Sleep mode by using I2C or SPI. When I ² C or SPI is used the user will transition by setting PPG Sequence. The sensor stays in this mode until the user transitions back to Sleep mode for power saving by read ID and write 0x00 to bank2 addr0x70, then SW reset and setting Sleep initial setting.
Touch ³	This mode is touch detection from Sleep mode by using I2C or SPI. When I ² C or SPI is used the user will transition by setting Touch Detection Sequence. The sensor stays in this mode until the user transitions back to Sleep mode for power saving by read ID and write 0x00 to bank2 addr0x70, then SW reset and setting Sleep initial setting.

Notes:

- 1. Refer to Sleep Mode Sequence for Power Saving section.
- 2. Refer to Obtaining Heart Rate PPG Raw Data Sequence section.
- 3. Refer to IR Touch Detection Sequence section.

5.2 Power-up and Power-off Sequence

The power up and power off sequence is illustrated in Figure 14. Please note:

- 1. There is no specific power supply voltage rise or fall time requirement.
- 2. Toggling RESET_N with steady supply voltages triggering a Reset.
- 3. I²C slave address will take effect only after a Reset.

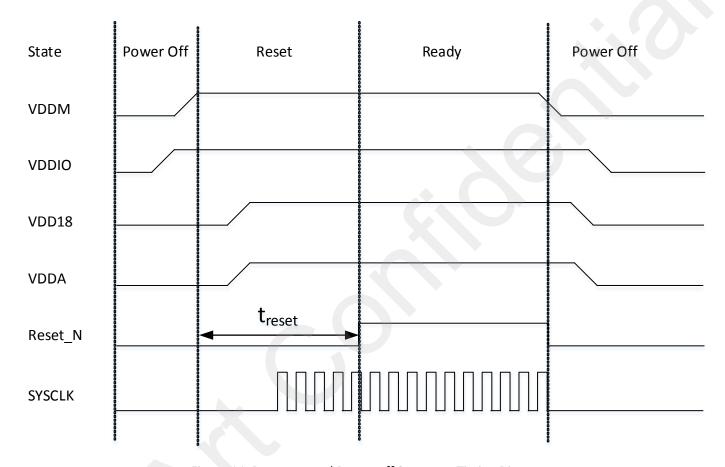


Figure 14. Power-up and Power-off Sequence Timing Diagram

6.0 I²C Serial Interface Communication

6.1 Signal Description

The two wires used for interface communication in PAH8002 are SCL (clock) and SDA (data). The PAH8002 is implemented as a slave-only device, so it never drives SCL, and only drives SDA during read cycles and transfer acknowledge bits. PAH8002 uses 7-bit 0x15 addressing and does not support clock stretching.

Table 9. I²C Signals Description

Signal Name	Label	Туре	Reset State	Description
Serial Clock	SPI_SCLK_I2C_SCL	Input	Input	The SCL signal is always driven by the master. SCL synchronizes the serial transmission of data bits on SDA. The frequency of SCL may vary throughout a transfer, as long as it meets all timing requirements.
Serial Data	SPI_SDI_I2C_SDA	Bi-Directional	Pull-up with 10K resistor	The SDA signal is for the host (master) to read from or write to the PAH8002. The host (typically a microcontroller) drives SCL and SDA in a write operation to, or when requesting information from the PAH8002.
				PAH8002 drives the SDA under two conditions: When responding with an acknowledge (ACK) bit after receiving data from the host, or When sending data to the host at the host's request. Data is sent in eight-bit packets

6.2 Start and Stop of Synchronous Operation

All communications take 9 clocks to complete, 8 for the data and the 9th bit is for acknowledge. Transfers are initiated with an S condition and terminated with the P condition. During the 8 bits of data transmissions, SDA may change while clock is low. SDA changing while clock is high is the S or P condition.

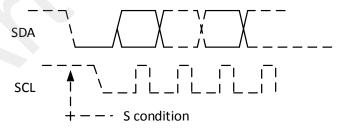


Figure 15. I²C S Conditions

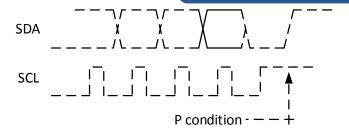


Figure 16. I²C P Conditions

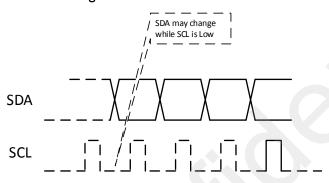


Figure 17. Data may change when SCL is low

Bytes that are transferred from the master to the slave are acknowledged by the slave. The slave acknowledges by driving a 0 on SDA during the 9th clock. This includes write data and slave address packets. When a byte is transferred from the slave to the master (read data), the slave ignores the SDA pin during the 9th clock.

When packets are sent over the I²C interface, they are generally of the format. The rnw (read_not_write) bit defines the direction of all data bytes after the S condition. In other words, it is not possible to initiate a write operation, and then switch to a read operation without completing the write.

S, <slave address, rnw>, A, data, A, data, A, ..., P

After a start condition, a single acknowledge/not acknowledge bit follows each eight-bit data packet. The device receiving the data drives the acknowledge/not acknowledge signal on SDA. Acknowledge (ACK) is defined as 0 and not acknowledge (NAK) is defined as 1.

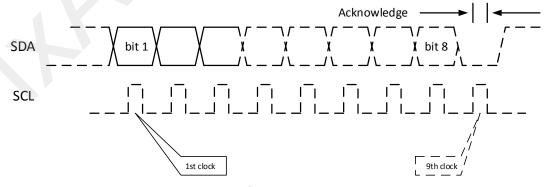


Figure 18. I²C Acknowledge bit

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6.3 Packet Formats

Read and write operations between the host and the PAH8002 use three types of host driven packets. All packets are eight bits long, with the most significant bit first, followed by an acknowledge bit.

- Slave Device Address (DA): Command packets contain a 7-bit device address and an read/write bit (R/W)
- Register Address Packets (RA): The address packets contain an 8-bit register address
- Data Packet (DP): Contains 8 data bits, and may be sent by the host or the PAH8002

Table 10. Packet Formats

Slave Device A	Address								
DA[6]	DA[5]	DA[4]	DA[3]	DA[2]	DA[1]	DA[0]	0: Write 1: Read		
Register Addre	Register Address								
RA[7]	RA[6]	RA[5]	RA[4]	RA[3]	RA[2]	RA[1]	RA[0]		
Register Data									
DP[7]	DP[6]	DP[5]	DP[4]	DP[3]	DP[2]	DP[1]	DP[0]		

6.4 Driven Packets

For a host driven packet, the host initiates all data transmission with a START condition. Next, slave address and register address packets are sent. If there is a device address match, the PAH8002 then responds to each Eight-bit data transmission with an acknowledge signal (SDA = 0). Data is transmitted with the most significant bit first. To terminate the transfer of host driven packets, the host follows the PAH8002's ACK with a STOP condition. The host can also issue a START condition after the PAH8002's ACK, if it wants to start a new data transfer.



Figure 19. I²C Host Driven Packet (Write)

For a PAH8002 driven packet, by request of the host, the PAH8002 acknowledges a read request, and then outputs a data byte transmitting the most significant bit (7) first. If the host intends to continue the data transfer, the host acknowledges the PAH8002. If the host intends to terminate the transfer, it responds with not acknowledge (SDA = 1), and then drives SDA to generate a STOP condition. The host can also drive a START condition, if it wants to begin a new data transfer with the same PAH8002.



Figure 20. I²C Slave Driven Packet (Read)



Figure 21. I²C slave driven packet (burst read)

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6.5 I²C Timing

Table 11. I²C Timing Specifications

Demande	Cumbal	Standard Mode		Fast Mode		Heit
Parameters	Symbol	Min.	Max.	Min.	Max.	Unit
SCL clock frequency.	f_{scl}	10	100	10	400	kHz
Hold time for Start/Repeat Start. After this period, the first clock pulse is generated.	t _{HD.STA}	4		0.6	< (7)	μs
Set-up time for a repeated Start.		4.7		0.6		μs
Low period of SCL clock.	t_{LOW}	4.7		1.3		μs
High period of SCL clock.	t _{HIGH}	0.75		0.6		μs
Data hold time.	t _{HD.DAT}	0		0		μs
Data set-up time.	t _{SU.DAT}	250		100		ns
Rise time of both SDA and SCL signals.	t _r		1000	-	300	ns
Fall time of both SDA and SCL signals.	t _f		300		300	ns
Set-up time for STOP condition.	t _{su.sto}	4		0.6		μs
Bus free time between a STOP and START.	t _{BUF}	4.7		1.3		μs

Notes:

1. Maximum current is 5mA and capacitance load spec. =100pF

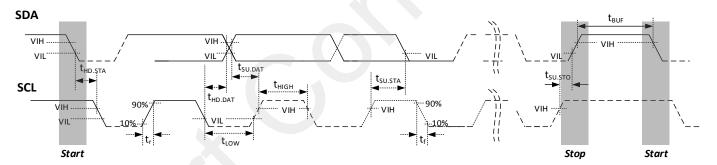


Figure 22. I²C Timing Diagram

7.0 Four-Wire SPI Serial Interface Communication

7.1 Signal Description

The four wires used for interface communication in PAH8002 are CSN (chip select), SCLK (clock), SDI (MOSI data) and SDO (MISO data). The PAH8002 is implemented as a slave-only device, so it never drives SCLK, and only drives SDO during read cycles.

Table 12. SPI Signals Description

Signal Name	Label	Туре	Reset State	Description
Chip Select	SPI_CSN	Input	Input	The CSN signal is always driven by the master and active low.
Serial Clock	SPI_SCLK_I2C_SCL	Input	Input	The SCLK signal is always driven by the master. All data changes on SPI_SDI/SPI_SDO are latched at SCLK rising edge. The frequency of SCLK may vary throughout a transfer, as long as it meets all timing requirements.
Serial Data	SPI_SDI_I2C_SDA	Input	Input	The SDI (MOSI) signal is for the host (master) to write to the PAH8002. The host (master) drives SCLK and SDI (MOSI) in a write operation to the PAH8002.
Serial Data	SPI_SDO	Output	Output	The SDO (MISO) signal is for the host (master) to read from the PAH8002. The host (master) drives SCLK and SDI when requesting information from SDO of the PAH8002.

7.2 Packet Formats

The transmission protocol consists of the two operation modes:

- Write Operation.
- Read Operation.

Both of the two operation modes consist of two bytes. The first byte contains the address (seven bits) and has bit-7 as its MSB to indicate data direction. The second byte contains the data.

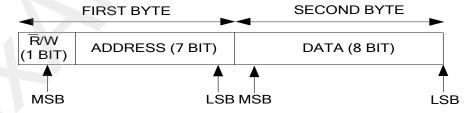


Figure 23. Four-wire SPI Transmission protocol

7.3 Driven Packets

7.3.1 Write Operation

A write operation is always initiated by the host controller and consists of two bytes, which the data is going from the host controller to the sensor. The first byte contains the 7 bits address and has a "1" as its MSB to indicate data direction. The second byte contains the full 8 bits data. This transfer is synchronized by SPI_SCLK_I2C_SCL. The host controller changes SPI_SDI_I2C_SDA at the falling edge of SPI_SCLK_I2C_SCL, while the sensor reads SPI_SDI_I2C_SDA at the rising edge of SPI_SCLK_I2C_SCL.

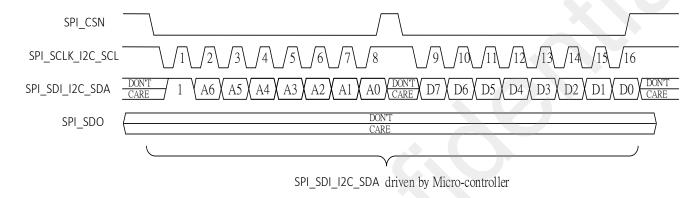


Figure 24. Four-wire SPI Write operation

7.3.2 Read Operation

A read operation is always initiated by the host controller and consists of two bytes, which the data is going from the sensor to the host controller. The first byte contains the 7 bits address that is written by the controller, and has a "0" as its MSB to indicate data direction. The second byte contains the full 8 bits data and is driven by the sensor. This transfer is synchronized by SPI_SCLK_12C_SCL.

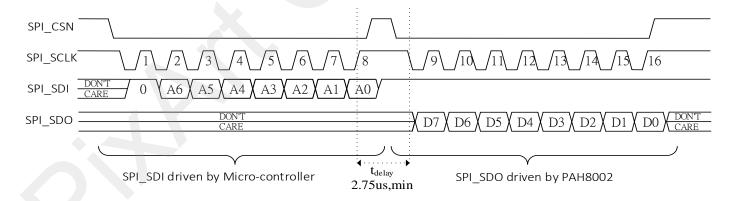


Figure 25. Four-wire SPI Read Operation

7.3.3 Switch Bank

For four-wire SPI interface, when the Read/Write Register addressing is beyond 0x7F in the Bank0, Bank1 and Bank2, the Switch Bank rule of (X+4) must be followed, where X is the bank number = 0, 1 and 2.

For example:

To read the data of BankO AddrOxE1, the following sequence shows the rule of bank switching from BankO to Bank4.

- 1. Write 0x04 to Addr0x7F //switch to Bank4
- 2. Read Addr0xE1 data

7.4 SPI Timing

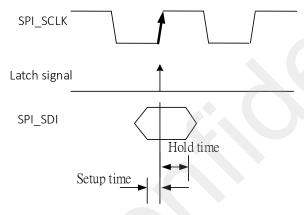


Figure 26. SPI Timing

Table 13. SPI Timing

Parameters	Symbol	Min	Max	Unit
Serial Host Write data bus setup time	Setup time	1/8 T		ns
Serial Host Write data bus hold time	Hold time	1/4 T		ns

Note: T = SPI clock (SPI_SCLK)

8.0 Digital SOC Function Control

8.1 Auto Exposure Control (AEC)

For the coverage of different human skin colors and tones, the sensor self-adjusts the exposure time and LED DAC current to optimize for the best brightness operating range.

- Three LED channels are controlled independently and output continuous signals. Refer to 0 registers section on the LED channels setting.
- Maximum exposure time is the value of AE_CHx_Max register and minimum exposure time is the value of AE_CHx_Min register. Refer to 10.3.3 registers section for the exposure time configuration.
- Maximum LED DAC current is set in LEDx_DAC_Code register and minimum LED DAC current is set in AE_LEDx_DAC_Min register. Refer to 10.6.5 and 10.6.6 registers section.

Example of Operating Range for Ch0 with bank0 0x77-0x7E registers and 1 sampling number.

- Bank0 0x77 and 0x78 is Outer Hi Bound, set value is 3072.
- Bank0 0x79 and 0x7A is Outer Low Bound, set value is 2048.
- Bank0 0x7B and 0x7C is Inner Hi Target, set value is 2816.
- Bank0 0x7D and 0x7E is Inner Low Target, set value is 2304.

Thus, ADC data convergence range is between 2048 and 3072. (2560 ± 512)

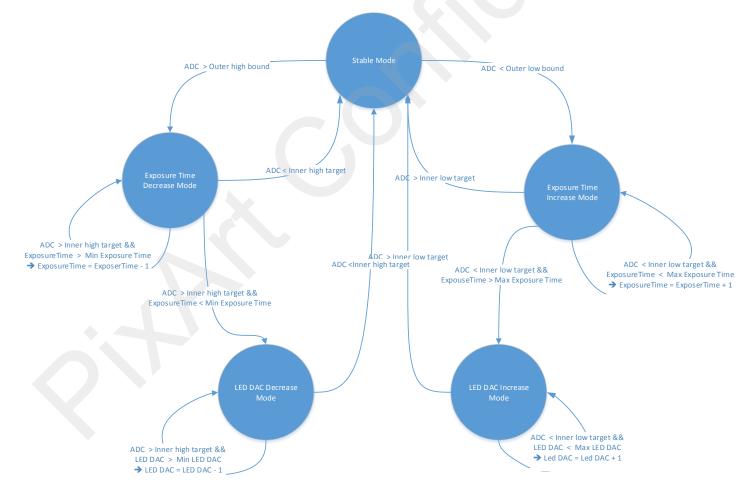


Figure 27. Auto Exposure Control Diagram

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Table 14. Register Reference of Enabling AEC

Bank	Address	Register Name	Description		
	0x77, 0x78	AE_CH0_Outerbound_Hi			
	0x9A, 0x9B	AE_CH1_Outerbound_Hi	Auto exposure outer high bound of CH0/1/2		
	0xBC, 0xBD	AE_CH2_Outerbound_Hi			
	0x7B, 0x7C	AE_CHO_Innertarget _Hi			
	0x9E, 0x9F	AE_CH1_Innertarget _Hi	Auto exposure inner high target of CH0/1/2		
	0xC0, 0xC1	AE_CH2_Innertarget _Hi			
	0x7D, 0x7E	AE_CHO_Innertarget_Lo			
	0xA0, 0xA1	AE_CH1_Innertarget_Lo	Auto exposure inner low target of CH0/1/2		
	0xC2, 0xC3	AE_CH2_Innertarget_Lo			
•	0x79, 0x7A	AE_CH0_Outerbound_Lo			
0	0x9C, 0x9D	AE_CH1_Outerbound_Lo	Auto exposure outer low bound of CH0/1/2		
	OxBE, OxBF	AE_CH2_Outerbound_Lo			
	0x6F, 0x70	AE_CH0_Max	Auto ava acuma tima a fam tha magaineuma haumad af		
	0x92, 0x93	AE_CH1_Max	Auto exposure time for the maximum bound of CHO/1/2		
	0xB4, 0xB5	AE_CH2_Max	Citofif2		
	0x71, 0x72	AE_CH0_Min	Automorphic for the majority and of		
	0x94, 0x95	AE_CH1_Min	Auto exposure time for the minimum bound of CH0/1/2		
	0xB6, 0xB7	AE_CH2_Min	C(10) 1/2		
	0x85	AE_LED0_DAC_Min	Auto LED DAG control for the main income housed of		
	0xA7	AE_LED1_DAC_Min	Auto LED DAC control for the minimum bound of CH0/1/2		
	0xC9	AE_LED2_DAC_Min	C(10) 1/ 2		
	OxBA	LED0_DAC_Code	Auto LED DAC control for the magning up have def		
1	OxBB	LED1_DAC_Code	Auto LED DAC control for the maximum bound of CH0/1/2		
	0xBC	LED2_DAC_Code	C(10) 1/2		

Table 15. Register Reference of Disabling AEC

Bank	Address	Register Name	Description		
0	0x6C	AE_CH0_EnH			
	0x8F	AE_CH1_EnH	Disable Auto Exposure for CH0/1/2		
	0xB1	AE_CH2_EnH			
	OxOD, OxOE	Ch0_Man_ET	Manual set of fixed exposure time for CH0/1/2		
	0x0F, 0x10	Ch1_Man_ET			
	0x11, 0x12	Ch2_Man_ET			
1	0xBA	LED0_DAC_Code			
	OxBB	LED1_DAC_Code	Manual set of fixed LED DAC current for CH0/1/2		
	0xBC	LED2_DAC_Code]		

Note: When disabling AE, the sensor will be fixed LED DAC current and exposure time. Refer to 10.3.3, 10.6.6 and 10.3.1 registers section.

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8.2 Heart Rate Detection

Heart rate detection is an optical measurement technique that uses a light source and a detector to detect cardiovascular pulse wave that propagates through the body. The detected signal (pulse wave) called photoplethysmography and it is known as PPG/PTG. The PPG signal reflects the blood movement in the vessel, which goes from the heart to the fingertips through the blood vessels in a wave-like motion. Therefore, we can use this PPG signal to calculate heart rate.

This optical based technology could offer significant benefits in healthcare application as it is noninvasive, yet accurate and simple to use.

8.2.1 Applications

- Heart rate detection in general healthcare (Perfusion Index : Typ.1%)
- PPG Waveform

8.2.2 Heart Rate Detection Performance

Parameters	Value	Unit	Conditions
Heart Rate Measurement Range	30 - 240	bpm	
Heart Rate Tolerance of Root	±3	bpm	@ Room temperature for steady state: 0 km/hr.
Mean Square (RMS)	±5		@ Room temperature for motion state: $0-9$ km/hr on the treadmill.
Response Time	8 - 10	second	@ Heart Rate = 72/bpm

Notes:

- PAH8002EP can provide heart rate measurement. However, it is not for medical device usage.
- For usage of heart rate detection sensor on the wearable device that to be put on the wrist, finger or palm,
 - The sensor must be placed securely and in-contact with the skin surface as well as keeping it stable without any motion during measurement in acquiring accurate heart rate measurement.
 - Do not wear the device on the wrist bone. It should be wear on the higher position of, especially for those with a smaller wrist.
- Sensor's performance is optimized with good blood flow. It is recommended to have light exercise for a few minutes to increase your blood flow before turning on the heart rate monitor.
- On cold weather condition or user is having poor blood circulation (e.g.: cold hands, fingers and feet), the sensor performance (heart rate accuracy) could be effected as the blood flow is slower in the measuring spot position. It is recommended to activate the heart rate monitor in indoor use.
- If the sensor is having problem to read heart rate, may try to swap it on the other side of hand wrist to repeat the measurement.
- For continuous heart rate measurement, do minimize hand movement and extreme bending of the wrist.

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8.3 IR Touch Detection

To enable IR Touch Detection function, configure the touch detection upper threshold, lower threshold and count registers in the PAH8002EP. Touch detection count period is the same as report rate period. A Touch action is reported when ADC data is more than both the touch detection upper threshold and count thresholds. HW INT will be triggered when change status from No Touch to Touch and from Touch to No Touch. A No Touch action is reported when ADC data is lower than touch detection lower threshold but above count threshold. Refer to 10.8 registers section.

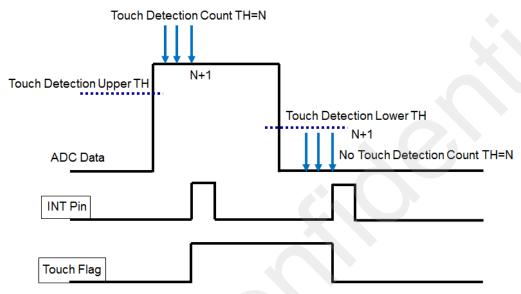


Figure 28. Touch Detection for INT Application

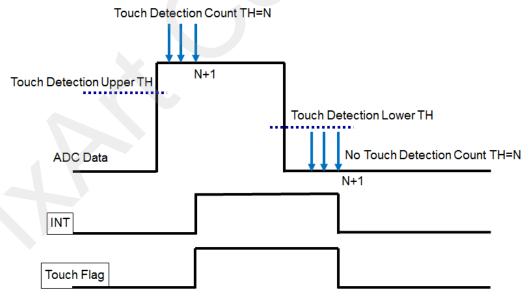


Figure 29. Touch Detection for Touch Flag Application

9.0 Operation Examples

9.1 IR Touch Detection Sequence

The following illustrates the steps to be in Touch mode.

- 1. Wake up Sensor (Read ID bank0 Addr0x00=0x02, Write 0x00 to Bank2 Addr0x70)
- 2. Run SW Reset (Write 0x00 to Bank0 Addr0xE1)
- 3. Load Touch setting for Touch mode. Refer to 11.1 and 11.2 appendix section.
- 4. Enable MCU interrupt.
- 5. Write 0x01 to Bank1 Addr0xD5 enable sensor.
- 6. Wait for touch interrupt.
- 7. When getting interrupt, execute (1.) action, then report touch status to MCU.

9.2 Obtaining Heart Rate PPG Raw Data Sequence with SRAM Buffer Mode

The following illustrates the steps to be in PPG mode.

- 1. Wake up Sensor (Read ID bank0 Addr0x00=0x02, Write 0x00 to Bank2 Addr0x70)
- 2. Run SW Reset (Write 0x00 to Bank0 Addr0xE1)
- 3. Load PPG setting of 20Hz for PPG mode. Refer to 11.3 appendix section.
- 4. Enable MCU interrupt.
- 5. Write 0x3D to Bank1 Addr0xEA set each 20 ADC data of three channels. Total is 3*20*4=240 bytes. FIFO data ready interval is 1 second for 20Hz report rate. Refer to 10.11 registers section.
- 6. Write 0x01 to Bank1 Addr0xD5 enable sensor.
- 7. Wait for FIFO interrupt.
- 8. When getting interrupt, execute (1.) action, then read out Bank3 Addr0x00 to get raw data from FIFO and clear interrupt (Write 0x01 to Bank2 Addr0x75, then Write 0x00 to Bank2 Addr0x75).
- 9. Exclusive or (XOR) FIFO data and compare with check sum register (burst read from bank2 Addr0x80~ Addr0x83)
- 10. Compare raw data and touch threshold to determine touch status.
- 11. Report PPG raw data and touch status to MCU.

9.3 Sleep Mode Sequence for Power Saving

The following illustrates the steps to be in sleep mode.

- 1. Wake up Sensor (Read ID bank0 Addr0x00=0x02, Write 0x00 to Bank2 Addr0x70)
- 2. Run SW Reset (Write 0x00 to Bank0 Addr0xE1)
- 3. Load Sleep setting for Sleep mode. Refer to 11.4 appendix section.
- 4. Write 0x01 to Bank1 Addr0xD5 enable sensor.

10.0 Registers

10.1 Registers List

Table 16. Register BankO

Note: Switch to Register BankO by writing 0x00 to Reg-0x7F

	Desister Name			Adduses	Dogistov Noves	Λ	Default
Address	Register Name	Access	Default	Address	Register Name	Access	Default
0x00	Product_ID_LB	RO	0x02	0x6E	AE_ChO_Mid_HB	R/W	0x00
0x01	Product_ID_HB	RO	0x80	0x6F	AE_Ch0_Max_LB	R/W	0xF0
0x02	Version_ID	RO	0xDx	0x70	AE_Ch0_Max_HB	R/W	0x00
0x0D	Ch0_Man_ET_LB	R/W	0xC8	0x71	AE_Ch0_Min_LB	R/W	0x52
0x0E	ChO_Man_ET_HB	R/W	0x00	0x72	AE_Ch0_Min_HB	R/W	0x00
0x0F	Ch1_Man_ET_LB	R/W	0xA0	0x77	AE_Ch0_Outerbound_Hi_LB	R/W	0x00
0x10	Ch1_Man_ET_HB	R/W	0x00	0x78	AE_Ch0_Outerbound_Hi_HB	R/W	0x06
0x11	Ch2_Man_ET_LB	R/W	0x78	0x79	AE_Ch0_Outerbound_Lo_LB	R/W	0x00
0x12	Ch2_Man_ET_HB	R/W	0x00	0x7A	AE_Ch0_Outerbound_Lo_HB	R/W	0x02
0x16	Ana_BG	R/W	0x00	0x7B	AE_Ch0_Innertarget_Hi_LB	R/W	0x00
0x3B	Ch0_Samp_Num	R/W	0x32	0x7C	AE_Ch0_Innertarget_Hi_HB	R/W	0x05
0x3C	Ch1_Samp_Num	R/W	0x20	0x7D	AE_Ch0_Innertarget_Lo_LB	R/W	0x00
0x3D	Ch2_Samp_Num	R/W	0x20	0x7E	AE_Ch0_Innertarget_Lo_HB	R/W	0x03
0x47	ChO_Global_EnH	R/W	0x01	0x85	AE_LED0_DAC_Min	R/W	0x01
0x48	Ch1_Global_EnH	R/W	0x00	0x8E	AE_LED0_DAC_EnH	R/W	0x01
0x49	Ch2_Global_EnH	R/W	0x00	0x8F	AE_Ch1_EnH	R/W	0x01
0x4A	LEDO_Sub_EnH	R/W	0x00	0x90	AE_Ch1_Mid_LB	R/W	0xA0
0x4B	LED1_Sub_EnH	R/W	0x01	0x91	AE_Ch1_Mid_HB	R/W	0x00
0x4C	LED2_Sub_EnH	R/W	0x01	0x92	AE_Ch1_Max_LB	R/W	0xF0
0x4D	LED_OnOff_Swap	R/W	0x01	0x93	AE_Ch1_Max_HB	R/W	0x00
0x50	Normalized_Mode_EnL_1	R/W	0x00	0x94	AE_Ch1_Min_LB	R/W	0x52
0x51	Normalized_Mode_EnL_2	R/W	0x00	0x95	AE_Ch1_Min_HB	R/W	0x00
0x56	Normalized_Right_Shift	R/W	0x07	0x9A	AE_Ch1_Outerbound_Hi_LB	R/W	0x00
0x5A	Touch_Detect_EnH	R/W	0x00	0x9B	AE_Ch1_Outerbound_Hi_HB	R/W	0x06
0x5C	TouchDetection_Upper_TH_1	R/W	0x00	0x9C	AE_Ch1_Outerbound_Lo_LB	R/W	0x00
0x5D	TouchDetection_Upper_TH_2	R/W	0x02	0x9D	AE_Ch1_Outerbound_Lo_HB	R/W	0x02
0x5E	TouchDetection_Upper_TH_3	R/W	0x00	0x9E	AE_Ch1_Innertarget_Hi_LB	R/W	0x00
0x5F	TouchDetection_Upper_TH_4	R/W	0x00	0x9F	AE_Ch1_Innertarget_Hi_HB	R/W	0x05
0x60	TouchDetection_Lower_TH_1	R/W	0x80	0xA0	AE_Ch1_Innertarget_Lo_LB	R/W	0x00
0x61	TouchDetection_Lower_TH_2	R/W	0x00	0xA1	AE_Ch1_Innertarget_Lo_HB	R/W	0x03
0x62	TouchDetection_Lower_TH_3	R/W	0x00	0xA7	AE_LED1_DAC_Min	R/W	0x01
0x63	TouchDetection_Lower_TH_4	R/W	0x00	0xB0	AE_LED1_DAC_EnH	R/W	0x01
0x64	TouchDetection_Count_TH	R/W	0x0A	0xB1	AE_Ch2_EnH	R/W	0x01
0x65	NoTouchDetection_Count_TH	R/W	0x0A	0xB2	AE_Ch2_Mid_LB	R/W	0xA0
0x6C	AE_ChO_EnH	R/W	0x01	0xB3	AE_Ch2_Mid_HB	R/W	0x00
0x6D	AE_Ch0_Mid_LB	R/W	0xA0	0xB4	AE_Ch2_Max_LB	R/W	0xF0
		ı	I			<u> </u>	

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PixArt Imaging Inc.

Address	Register Name	Access Default		Address	Register Name	Access	Default
0xB5	AE_Ch2_Max_HB	R/W	0x00	0xC1	AE_Ch2_Innertarget_Hi_HB	R/W	0x05
0xB6	AE_Ch2_Min_LB	R/W	0x52	0xC2	AE_Ch2_Innertarget_Lo_LB	R/W	0x00
0xB7	AE_Ch2_Min_HB	R/W	0x00	0xC3	AE_Ch2_Innertarget_Lo_HB	R/W	0x03
0xBC	AE_Ch2_Outerbound_Hi_LB	R/W	0x00	0xC9	AE_LED2_DAC_Min	R/W	0x01
0xBD	AE_Ch2_Outerbound_Hi_HB	R/W	0x06	0xD2	AE_LED2_DAC_EnH	R/W	0x01
OxBE	AE_Ch2_Outerbound_Lo_LB	R/W	0x00	0xDE	PGAgain_Sel	R/W	0x01
0xBF	AE_Ch2_Outerbound_Lo_HB	R/W	0x02	0xE1	SW_Reset_N	R/W	0x01
0xC0	AE_Ch2_Innertarget_Hi_LB	R/W	0x00	0xE6	LED_DAC_Change_Flag_EnH	R/W	0x00

Table 17. Register Bank1

Note: Switch to Register Bank1 by writing 0x01 to Reg-0x7F

Address	Register Name	Access	Default	Address	Register Name	Access	Default
0x7A	BG_Sub_EnH	R/W	0x00	OxBB	LED1_DAC_Code	R/W	0x40
0x7C	Congain_Sel	R/W	0x00	0xBC	LED2_DAC_Code	R/W	0x40
0x80	PS_Ctrl_EnH	R/W	0x01	0xC0	LPT_EnH	R/W	0x01
0xB4	LEDO_Man_EnH	R/W	0x00	0xC3	OSC_EnL	R/W	0x00
0xB5	LED1_Man_EnH	R/W	0x00	0xD5	TIMER_Gen_Enable	R/W	0x00
0xB6	LED2_Man_EnH	R/W	0x00	0xD6	TIMER_Gen_Period_LB	R/W	0x40
0xB7	LED0_DAC_EnL	R/W	0x00	0xD7	TIMER_Gen_Period_HB	R/W	0x01
0xB8	LED1_DAC_EnL	R/W	0x00	0xE6	IF_Wakeup_Interval_LB	R/W	0x05
0xB9	LED2_DAC_EnL	R/W	0x00	0xE7	IF_Wakeup_Interval_HB	R/W	0x00
0xBA	LED0_DAC_Code	R/W	0x40	0xEA	SetFIFO_RptNum	R/W	0x03

Table 18. Register Bank2

Note: Switch to Register Bank2 by writing 0x02 to Reg-0x7F

Address	Register Name	Access	Default	Address	Register Name	Access	Default
0x25	INT_Mode_Sel	R/W	0x00	0x83	Readout_FIFO_Checksum_4	RO	0x00
0x29	INT_Output_EnL	R/W	0x01	0x8C	INT_SramFIFO_Overflow_Clear	R/W	0x00
0x45	Touch_Flag	RO	0x00	0x8D	INT_SramFIFO_Overflow_Mask	R/W	0x00
0x73	INT_Reg_Array	RO	0x00	0x8E	INT_SramFIFO_Underflow_Clear	R/W	0x00
0x74	INT_SramFIFO_DR_Mask	R/W	0x00	0x8F	INT_SramFIFO_Underflow_Mask	R/W	0x00
0x75	INT_SramFIFO_DR_Clear	R/W	0x00	0xA0	CHO_Exposure_Time_LB	RO	0x00
0x76	INT_TouchDet_Mask	R/W	0x00	0xA1	CH0_Exposure_Time_HB	RO	0x00
0x77	INT_TouchDet_Clear	R/W	0x00	0xA2	CH1_Exposure_Time_LB	RO	0x00
0x78	All_INT_Mask	R/W	0x00	0xA3	CH1_Exposure_Time_HB	RO	0x00
0x7A	INT_Type	R/W	0x01	0xA4	CH2_Exposure_Time_LB	RO	0x00
0x7B	INT_Pulse_Width	R/W	0x08	0xA5	CH2_Exposure_Time_HB	RO	0x00
0x80	Readout_FIFO_Checksum_1	RO	0x00	0xA6	LEDO_DAC_Value	RO	0x00
0x81	Readout_FIFO_Checksum_2	RO	0x00	0xA7	LED1_DAC_Value	RO	0x00
0x82	Readout_FIFO_Checksum_3	RO	0x00	0xA8	LED2_DAC_Value	RO	0x00

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10.2 Sensor Array Controls

Table 19. Sensor Array Controls Registers Usage Reference

Usage	Register Addresses	
PGA Gain	Bank0: 0xDE	
Background Subtraction	Bank1: 0x7A	
Conversion Gain	Bank1: 0x7C	

10.2.1 PGAgain_Sel Register

Register Name	PGAgain_Se	el							
Bank	0			Add	ress	0xDE	0xDE		
Access	R/W			Reset	Value	0x01	0x01		
Bit	7	6	5	4	3	2	1	0	
Field				Reserved PG/					
Description	Bit[0] is used	d for PGA ga	in factor cor	ntrol.					
Field	Access	Reset	Value			Description			
DCA Coin	D /\A/	1	0	1x					
PGA Gain	R/W	1	1	2x					

10.2.2 BG_Sub_EnH Register

Register Name	BG_Sub_En	G_Sub_EnH									
Bank	1	1			Address 0x7A						
Access	R/W			Reset	Reset Value 0x00						
Bit	7	6	5	4	3	2	1	0			
Field				Reserved		BG_Sub					
Description	Bit[0] is used	to enable b	ackground s	ubtraction.							
Field	Access	Reset	Value			Description					
DC Cub	R/W		0	Disable							
BG_Sub	K/VV	0	1	Enable							

10.2.3 Congain_Sel Register

Register Name	Congain_Se	Congain_Sel								
Bank	1			Add	Address 0x7C					
Access	R/W			Reset	Value	0x00				
Bit	7	6	5	4	3	2	1	0		
Field				Reserved		Congain				
Description	Bit[0] is used	d for convers	sion gain fac	tor control.						
Field	Access	Reset	Value			Description				
Congoin	R/W	0	0	4x						
Congain	r/ VV	U	1	1x						

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10.3 Image Sensor Core Digital Controls

Table 20. Image Sensor Core Digital Registers Usage Reference

Usage	Register Addresses	
Channel Exposure Time	Bank0: 0x0D – 0x12,	
Analog Background Subtraction Mode	Bank0: 0x16	
Auto Exposure Controls	Bank0: 0x6C – 0x72, 0x8F – 0x95, 0xB1 – 0xB7	
Auto Exposure Convergence Range	Bank0: 0x77-0x7E, 0x9A-0xA1, 0xBC-0xC3	

10.3.1 Channel Exposure time

10.3.1.1 CHO Man ET Register

Register Name	Ch0_Man_	ET LB									
Bank	0	_		Add	dress	0x0D					
Access	R/W Reset Value 0xC8										
Bit	7	6	5	4	3	2	1	0			
Field		Ch0_Man_ET[7:0]									
Register Name	Ch0_Man_E	Ch0_Man_ET_HB									
Bank	0			Add	dress	0x0E					
Access	R/W			Reset	Value	0x00					
Bit	7	6	5	4	3	2	1	0			
Field				Ch0_Man	_ET[15:8]		•				
Doscription				0 Channel. Ch its.Each bit st		[7:0] are the l s.	ower 8bits an	d			
Description	Reset value	$0 \times 0000000000000000000000000000000000$	00								
	Default exp	osure time =	62.5ns x 200	0 = 12500ns =	: 12.5µs						

10.3.1.2 CH1_Man_ET Register

Register Name	Ch1_Man_E	T_LB								
Bank	0			Add	lress	0x0F				
Access	R/W			Reset	Value	0xA0				
Bit	7	6	5	4	3	2	1	0		
Field		Ch1_Man_ET[7:0]								
Register Name	Ch1_Man_E	Ch1_Man_ET_HB								
Bank	0			Address		0x10				
Access	R/W			Reset	Value	0x00				
Bit	7	6	5	4	3	2	1	0		
Field				Ch1_Man	_ET[15:8]					
		•		1 Channel. Ch		-	ower 8bits an	d		
Description	Ch1_Man_ET[15:8] are the upper 8bits. Each bit step is 62.5ns.									
·		0x00A0 = 16	-							
	Default expo	osure time: 6	2.5ns x 160	= 10000ns = 1	L0.0μs					

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10.3.1.3 CH2_Man_ET Register

Register Name	Ch2_Man_I	ET_LB									
Bank	0			Add	lress	0x11					
Access	R/W			Reset	Value	0x78					
Bit	7	6	5	4	3	2	1	0			
Field		Ch2_Man_ET[7:0]									
Register Name	Ch2_Man_E	Т_НВ									
Bank	0			Address		0x12					
Access	R/W			Reset	Value	0x00	Ox00				
Bit	7	6	5	4	3	2	1	0			
Field				Ch2_Man	_ET[15:8]						
	Manual set	of exposure	time for LED	2 Channel. Ch	12_Man_ET[7	:0] are the lo	wer 8bits an	d			
Description	Ch2_Man_ET[15:8] are the upper 8bits. Each bit step is 62.5ns.										
Description	Reset value	0x0078 = 12	20								
	Default exp	osure time: 6	2.5ns x 120	= 7500ns = 7.	5μs						

10.3.2 Analog Background Subtraction

10.3.2.1 Analog Background Subtraction Mode Register

Register Name	Ana_BG	Ana_BG									
Bank	0			Add	Address		0x16				
Access	R/W			Reset	: Value	0x00					
Bit	7	6	5	4	3	2	1	0			
Field				Reserved				Ana_BG			
Description				ckground sub de is enabled,			bit to 1 man	ually. Refer			
Field	Access	Reset	Value	ue Description							
Ana PG	R/W	0	0	Disable							
Ana_BG	11/ VV	U	1	Enable							

10.3.3 Auto Exposure Control

10.3.3.1 AE_CHO_EnH Register

Register Name	AE_CH0_En	Н							
Bank	0 Address					0x6C	0x6C		
Access	R/W			Reset	Value	0x01			
Bit	7	6	5	4	3	2	1	0	
Field				Reserved				AE_CH	
Description	Bit[0] is used	d to enable A	Auto Exposu	re for Channel	l 0.				
Field	Access	Reset	Value			Description			
AE CH	D ///	1	0	Disable					
AE_CH	R/W	1	1	Enable					

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10.3.3.2 AE_CHO_Mid Register

Register Name	AE_CH0_M	id_LB							
Bank	0			Add	lress	0x6D			
Access	R/W			Reset	: Value	0xA0			
Bit	7	6	5	4	3	2	1	0	
Field				AE_CH0_	Mid[7:0]	•			
Register Name	AE_CH0_M	id_HB					• (Λ	
Bank	0			Add	dress	0x6E			
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field				AE_CH0_I	Mid[15:8]				
Description		•		the middle bo are the upper		nnel 0. AE_CH	0_Mid[7:0] a	are the	

10.3.3.3 AE_CHO_Max Register

Register Name	AE_CH0_M	ax_LB							
Bank	0			Add	dress	0x6F			
Access	R/W			Reset	: Value	0xF0	0xF0		
Bit	7	6	5	4	3	2	1	0	
Field				AE_CH0_	Max[7:0]				
Register Name	AE_CH0_M	ax_HB							
Bank	0			Add	dress	0x70			
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field				AE_CHO_N	Max[15:8]				
Description				the maximum are the upper		hannel 0. AE_	CH0_Max[7:	O] are the	

10.3.3.4 AE_CHO_Min Register

Register Name	AE_CH0_Mi	in_LB							
Bank	0			Add	dress	0x71			
Access	R/W			Reset	t Value	0x52	0x52		
Bit	7	6	5	4	3	2	1	0	
Field				AE_CH0_	Min[7:0]				
Register Name	AE_CH0_Mi	in_HB							
Bank	0			Add	dress	0x72			
Access	R/W			Reset	t Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field				AE_CH0_I	Min[15:8]				
Description		-		the minimum re the upper		hannel 0. AE_	CH0_Min[7:0] are the	

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10.3.3.5 AE_CH1_EnH Register

Register Name	AE_CH1_En	Н									
Bank	0			Add	lress	0x8F	0x8F				
Access	R/W			Reset	Value	0x01					
Bit	7	6	5	4	3	2	1	0			
Field				Reserved				AE_CH1			
Description	Bit[0] is used	d to enable A	Auto Exposu	re for Channel	1.		\				
Field	Access	Reset	Value			Description					
A.F. C.I.1	D/M/	1	0	Disable							
AE_CH1	R/W	1	1	Enable							

10.3.3.6 AE_CH1_Mid Register

Register Name	AE_CH1_M	id_LB						
Bank	0			Ado	dress	0x90		
Access	R/W Reset Value 0xA0							
Bit	7	6	5	4	3	2	1	0
Field				AE_CH1_	Mid[7:0]			
Register Name	AE_CH1_M	id_HB						
Bank	0			Add	lress	0x91		
Bank Access	0 R/W				lress : Value	0x91 0x00		
-	_	6	5				1	0
Access	_	6	5	Reset	Value 3		1	0

10.3.3.7 AE_CH1_Max Register

Register Name	AE_CH1_M	ax_LB							
Bank	0			Add	dress	0x92	0x92		
Access	R/W			Reset	: Value	0xF0			
Bit	7	6	5	4	3	2	1	0	
Field				AE_CH1_	Max[7:0]				
Register Name	AE_CH1_M	ax_HB							
Bank	0			Add	dress	0x93			
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field				AE_CH1_N	Max[15:8]				
Description		Set the AE control exposure time for the maximum bound of Channel 1. AE_CH1_Max[7:0] are the ower 8bits and AE_CH1_Max[15:8] are the upper 8bits.						O] are the	

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10.3.3.8 AE_CH1_Min Register

Register Name	AE_CH1_M	in_LB								
Bank	0			Ade	dress	0x94				
Access	R/W			Rese	t Value	0x52				
Bit	7	6	5	4	3	2	1	0		
Field				AE_CH1_	_Min[7:0]					
Register Name	AE_CH1_M	in_HB					• (
Bank	0			Ado	dress	0x95				
Access	R/W			Rese	t Value	0x00				
Bit	7	6	5	4	3	2	1	0		
Field				AE_CH1_	Min[15:8]					
Description		t the AE control exposure time for the minimum bound of Channel 1. AE_CH1_Min[7:0] are the wer 8bits and AE_CH1_Min[15:8] are the upper 8bits.								

10.3.3.9 AE_CH2_EnH Register

Register Name	AE_CH2_En	Н						
Bank	0			Add	ress	0xB1		
Access	R/W			Reset	Value	0x01		
Bit	7	6	5	4	3	2	1	0
Field				Reserved				AE_CH2
Description	Bit[0] is used	d to enable A	Auto Exposu	re for Channel	2.			
Field	Access	Reset	Value			Description		
AE CH3	D ///	1	0	Disable				
AE_CH2	R/W	1	1	Enable				_

10.3.3.10 AE_CH2_Mid Register

Register Name	AE_CH2_M	id_LB							
Bank	0			Add	dress	0xB2			
Access	R/W			Reset	: Value	0xA0	0xA0		
Bit	7	6	5	4	3	2	1	0	
Field				AE_CH2_	Mid[7:0]				
Register Name	AE_CH2_M	id_HB							
Bank	0			Add	dress	0xB3			
Access	R/W			Reset	: Value	0x00	0x00		
Bit	7	6	5	4	3	2	1	0	
Field				AE_CH2_ſ	Mid[15:8]			_	
Description		•		the middle bo re the upper		nnel 2. AE_CH	l2_Mid[7:0] a	re the	

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10.3.3.11 AE_CH2_Max Register

Register Name	AE_CH2_M	ax_LB						
Bank	0			Add	Iress	0xB4		
Access	R/W			Reset	Value	0xF0		
Bit	7	6	5	4	3	2	1	0
Field				AE_CH2_	Max[7:0]			
Register Name	AE_CH2_M	ax_HB						
Bank	0			Add	lress	0xB5		
						0x00		
Access	R/W			Reset	: Value	0x00		
Access Bit	R/W 7	6	5	Reset 4	Value 3	0x00 2	1	0
	R/W 7	6	5	Reset 4 AE_CH2_N	3	2	1	0

10.3.3.12 AE_CH2_Min Register

Register Name	AE_CH2_M	in_LB						
Bank	0			Add	dress	0xB6		
Access	R/W			Reset	Value	0x52		
Bit	7	6	5	4	3	2	1	0
Field				AE_CH2_	Min[7:0]			
Register Name	AE_CH2_M	in_HB						
D I.				رايد ٨ ما .	1	007		
Bank	0			Add	dress	0xB7		
Access	0 R/W				ress : Value	0x00		
		6	5				1	0
Access		6	5		Value 3		1	0

10.3.4 Auto Exposure Convergence Range

10.3.4.1 AE_CHO_Outerbound_Hi Register

Register Name	AE_CHO_Ou	terbound_H	li_LB						
Bank	0			Add	dress	0x77			
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field		AE_CH0_Outerbound_Hi[7:0]							
Register Name	AE_CH0_Ou	AE_CH0_Outerbound_Hi_HB							
Bank	0			Add	dress	0x78			
Access	R/W			Reset	: Value	0x06			
Bit	7	6	5	4	3	2	1	0	
Field			AE	_CH0_Outerl	oound_Hi[1	5:8]			
Description		AE_CHO_Outerbound_Hi[15:8] et the AE convergence range for the outer high bound of Channel 0. AE_CHO_Outerbound_Hi [7:0] re the lower 8bits and AE_CHO_Outerbound_Hi [15:8] are the upper 8bits.							

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10.3.4.2 AE_CH0_Outerbound_Lo Register

Register Name	AE_CH0_Ou	AE_CH0_Outerbound_Lo_LB									
Bank	0	0 Address 0x79									
Access	R/W Reset Value 0x00										
Bit	7	6	5	4	3	2	1	0			
Field			AE	_CH0_Outer	bound_Lo[7:	0]					
Register Name	AE_CH0_O	AE_CH0_Outerbound_Lo_HB									
Bank	0			Add	lress	0x7A					
Access	R/W			Reset	Value	0x02					
Bit	7	6	5	4	3	2	1	0			
Field			AE	_CH0_Outerb	ound_Lo[15	:8]					
	Cot the AF or	AE_CH0_Outerbound_Lo[15:8] Set the AE convergence range for the outer low bound of Channel 0. AE_CH0_Outerbound_Lo [7:0] are the lower 8bits and AE_CH0_Outerbound_Lo [15:8] are the upper 8bits.									

10.3.4.3 AE_CH0_Innertarget_Hi Register

Register Name	AE_CH0_In	nertarget_H	i_LB					
Bank	0			Add	lress	0x7B		
Access	R/W Reset Value 0x00							
Bit	7	6	5	4	3	2	1	0
Field			А	E_CH0_Inner	target_Hi[7:0)]		
Register Name	AE_CH0_In	nertarget_H	i_HB					
Bank	0			Add	lress	0x7C		
Access	R/W			Reset	Value	0x05		
Di+	_	_	5	4	•	1	1	0
Bit	/	6	5	4	3		1	ס
Field		Ь		4 CH0_Innert		8]	Т	0

10.3.4.4 AE_CHO_Innertarget_Lo Register

Register Name	AE_CH0_Ini	nertarget_Lo	_LB						
Bank	0	O Address 0x7D							
Access	R/W Reset Value 0x00								
Bit	7	6	5	4	3	2	1	0	
Field			А	E_CH0_Inner	target_Lo[7:0)]			
Register Name	AE_CH0_Ini	AE_CH0_Innertarget_Lo_HB							
Bank	0			Add	Iress	0x7E			
Bank Access	0 R/W				lress Value	0x7E 0x03			
		6	5				1	0	
Access		6			Value 3	0x03	1	0	

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10.3.4.5 AE_CH1_Outerbound_Hi Register

Register Name	AE_CH1_O	uterbound_F	li_LB						
Bank	0			Add	dress	0x9A		_	
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field			Al	E_CH1_Outer	bound_Hi[7	:0]			
Register Name	AE_CH1_O	AE_CH1_Outerbound_Hi_HB							
Bank	0			Add	dress	0x9B			
Access	R/W			Reset	: Value	0x06			
Bit	7	6	5	4	3	2	1	0	
Field			AE	_CH1_Outer	oound_Hi[15	5:8]			
Description						nnel 1. AE_CH upper 8bits.	l1_Outerbou	ınd_Hi [7:0]	

10.3.4.6 AE_CH1_Outerbound_Lo Register

Register Name	AE_CH1_Oι	uterbound_L	.o_LB						
Bank	0			Add	lress	0x9C			
Access	R/W			Reset	Value	0x00	0x00		
Bit	7	6	5	4	3	2	1	0	
Field		AE_CH1_Outerbound_Lo[7:0]							
Register Name	AE_CH1_O	uterbound_L	.o_HB						
Bank	0			Add	Iress	0x9D			
Access	R/W			Reset	Value	0x02			
Bit	7	6	5	4	3	2	1	0	
Field			AE	_CH1_Outerb	ound_Lo[1	5:8]			
Description		_	•			nnel 1. AE_CH e upper 8bits.	_	nd_Lo [7:0]	

10.3.4.7 AE_CH1_Innertarget_Hi Register

Register Name	AE_CH1_Ini	nertarget_Hi	_LB						
Bank	0	0 Address 0x9E							
Access	R/W Reset Value 0x00								
Bit	7	6	5	4	3	2	1	0	
Field			А	E_CH1_Inner	target_Hi[7:0)]			
Register Name	AE_CH1_Ini	AE_CH1_Innertarget_Hi_HB							
	0 Address 0x9F								
Bank	0			Add	dress	0x9F			
Bank Access	O R/W				dress : Value	0x9F 0x05			
		6	5				1	0	
Access		6			Value 3	0x05 2	1	0	

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10.3.4.8 AE_CH1_Innertarget_Lo Register

Register Name	AE_CH1_Innertarget_Lo_LB									
Bank	0			Add	lress	0xA0	0xA0			
Access	R/W			Reset	Value	0x00				
Bit	7	6	5	4	3	2	1	0		
Field			А	E_CH1_Inner	target_Lo[7:0)]				
Register Name	AE_CH1_In	AE_CH1_Innertarget_Lo_HB								
Bank	0			Add	lress	0xA1				
Access	R/W			Reset	Value	0x03				
Bit	7	6	5	4	3	2	1	0		
Field			AE	_CH1_Innerta	arget _Lo[15:	8]				
Description		_	_	inner low tar rtarget _Lo [1	_		_Innertarget	_Lo [7:0]		

10.3.4.9 AE_CH2_Outerbound_Hi Register

Register Name	AE_CH2_Ou	uterbound_H	li_LB						
Bank	0			Add	dress	0xBC			
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field		AE_CH2_Outerbound_Hi[7:0]							
Register Name	AE_CH2_Ou	AE_CH2_Outerbound_Hi_HB							
Bank	0			Add	dress	0xBD			
Access	R/W			Reset	: Value	0x06			
Bit	7	6	5	4	3	2	1	0	
Field			AE	_CH2_Outerk	oound_Hi[15	5:8]			
Description		AE_CH2_Outerbound_Hi[15:8] et the AE convergence range for the outer high bound of Channel 2. AE_CH2_Outerbound_Hi [7:0] re the lower 8bits and AE_CH2_Outerbound_Hi [15:8] are the upper 8bits.							

10.3.4.10 AE_CH2_Outerbound_Lo Register

Register Name	AE_CH2_Outerbound_Lo_LB									
Bank	0			Add	lress	OxBE		_		
Access	R/W Reset Value 0x00									
Bit	7	6	5	4	3	2	1	0		
Field			AE	_CH2_Outer	bound_Lo[7:	0]				
Register Name	AE_CH2_Ou	uterbound_L	o_HB							
Bank	0			Ado	Iress	OxBF				
Access	R/W			Reset	Value	0x02				
Bit	7	6	5	4	3	2	1	0		
Field			AE	_CH2_Outerb	ound_Lo[15	:8]				
Description		•	_	outer low bo erbound_Lo [_	2_Outerbour	nd_Lo [7:0]		

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10.3.4.11 AE_CH2_Innertarget_Hi Register

Register Name	AE_CH2_Ini	nertarget_Hi	_LB						
Bank	0			Add	dress	0xC0		_	
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field			А	E_CH2_Inner	target_Hi[7:	0]			
Register Name	AE_CH2_Ini	AE_CH2_Innertarget_Hi_HB							
Bank	0			Add	dress	0xC1			
Access	R/W			Reset	: Value	0x05			
Bit	7	6	5	4	3	2	1	0	
Field			AE	_CH2_Innert	arget _Hi[15	:8]			
Description		_	_	inner high ta rtarget _Hi [1	_	nel 2. AE_CH2 upper 8bits.	2_Innertarge	t _Hi [7:0]	

10.3.4.12 AE_CH2_Innertarget_Lo Register

Register Name	AE_CH2_Ini	AE_CH2_Innertarget_Lo_LB								
Bank	0 Address 0xC2									
Access	R/W			Reset	Value	0x00				
Bit	7	6	5	4	3	2	1	0		
Field			А	E_CH2_Inner	target_Lo[7:0)]				
Register Name	AE_CH2_Ini	nertarget_Lo	_HB							
Bank	0			Add	lress	0xC3				
Access	R/W			Reset	Value	0x03		_		
Bit	7	6	5	4	3	2	1	0		
Field			AE	_CH2_Innerta	arget _Lo[15:	8]				
Description			•	inner low tar rtarget _Lo [1	~	_	_Innertarget	_Lo [7:0]		

10.4 Reset

10.4.1.1 SW_Reset Register

Register Name	SW_Reset_I	SW_Reset_N								
Bank	0			Ac	ddress	0xE1				
Access	R/W			Rese	et Value	0x01				
Bit	7	6	5	4 3 2 1				0		
Field	Reserved SW ₂						SW_Reset_N			
Description	Software res	et for all digi	ital blocks. S	ignal is Activ	e Low.					
Field	Access	Reset	Value			Descriptio	n			
CM/ Poset N	D /\/	1	0	Reset all digital blocks						
SW_Reset_N	R/W	1	1	In current	use-mode					

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10.5 Power Saving

10.5.1 PS_Ctrl_EnH Register

Register Name	PS_Ctrl_Enl	1							
Bank	1			Add	lress	0x80			
Access	R/W			Reset	Value	0x01	0x01		
Bit	7	6	5	4	3	2	1	0	
Field		Reserved PS_Ctr						PS_Ctrl	
Description			_	g mechanism f Mechanism se	_	power consu	mption of ana	alog and	
Field	Access	Reset	Value			Description			
DC C+=1	D /\\/	0	0	Disable					
PS_Ctrl	R/W	U	1	Enable			>		

10.5.2 Wakeup Interval Registers

Register Name	IF_Wakeup	_Interval_L	В						
Bank	1			Add	dress	0xE6			
Access	R/W			Reset	. Value	0x05			
Bit	7	6	5	4	3	2	1	0	
Field		IF_Wakeup_Interval [7:0]							
Register Name	IF_Wakeup	Wakeup_Interval_HB							
Bank	1	1			Address 0xE7				
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field				IF_Wakeup_Ii	nterval [15:	8]			
Description	will go to Sleep Time	eep mode.	_Interval [15	5:0] x 31.25μs		nd after Sleep ⁻	Time period,	the chip	

10.6 LED Controls

10.6.1 Channel Sampling Number

10.6.1.1 CHO_Sampling_Number Register

Register Name	CH0_Sampl	CHO_Sampling_Number							
Bank	0			Add	lress	0x3B			
Access	R/W			Reset	: Value	0x32			
Bit	7	6	5	4	3	2	1 0		
Field		CHO_Sampling_Number[7:0]							
Description	Set the LED	0 sampling ກເ	umber of Ch	annel 0.					

10.6.1.2 CH1_Sampling_Number Register

Register Name	CH0_Samp	CH0_Sampling_Number							
Bank	0			Addı	ress	0x3C			
Access	R/W			Reset Value 0x20					
Bit	7	6	5	4	3	2	1	0	
Field		CH1_Sampling_Number[7:0]							
Description	Set the LED	Set the LED1 sampling number of Channel 1.							

10.6.1.3 CH2_Sampling_Number Register

Register Name	CH0_Sampl	ling_Number	ſ		•				
Bank	0	/har			Address 0x3D				
Access	R/W			Reset Value 0x20					
Bit	7	6	5	4	3	2	1	0	
Field		CH2_Sampling_Number[7:0]							
Description	Set the LED	Set the LED2 sampling number of Channel 2.							

10.6.2 Channel Main Switch Enable

Sensor can support three channels and user can select to use either one, two or three channels.

10.6.2.1 CH0_Global_EnH Register

Register Name	CH0_Global	CH0_Global_EnH								
Bank	0			Add	lress	0x47				
Access	R/W			Reset	Value	0x01				
Bit	7	6	5	4	3	2	1	0		
Field	Reserved							CH0_Glob		
Description	Bit[0] is used	d for main sw	vitch enable	of Channel 0						
Field	Access	Reset	Value			Description				
CHO Glob	D /\\/	D/M 1		Disable						
	R/W 1		1	Enable						

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10.6.2.2 CH1_Global_EnH Register

Register Name	CH1_Global	_EnH						
Bank	0			Add	lress	0x48		
Access	R/W			Reset	Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field		Reserved						CH1_Glob
Description	Bit[0] is used	d for main sv	vitch enable	of Channel 1				
Field	Access	Reset	Value			Description		
CUO Clob	D /\\/	R/W 0 —		Disable				
CH0_Glob	r/VV			Enable				

10.6.2.3 CH2_Global_EnH Register

Register Name	CH2_Global	_EnH						
Bank	0				lress	0x49		
Access	R/W			Reset	Value	0x00		
Bit	7 6 5 4 3 2 1						0	
Field	Reserved							CH2_Glob
Description	Bit[0] is used	d for main sv	vitch enable	of Channel 2				
Field	Access	Reset	Value			Description		
CU2 Clob	D /\\/	5/4/		Disable				
CH2_Glob	R/W	0	1	Enable				

10.6.3 LED Frame Cycle Control

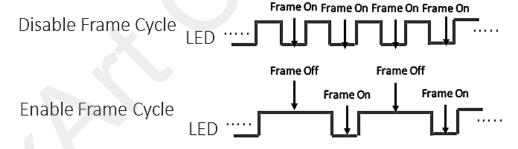


Figure 30. LED Frame Cycle Diagram

10.6.3.1 LEDO_Sub_EnH Register

Register Name	LED0_Sub_E	.ED0_Sub_EnH								
Bank	0			Add	lress	0x4A				
Access	R/W			Reset	Reset Value 0x00					
Bit	7	6 5 4 3 2 1					0			
Field	Reserved						LED0_Sub			
Description	Bit[0] is used	d to enable f	rame cycle c	of Channel 0			\			
Field	Access	Reset	Value			Description				
LEDO Cub	R/W 0		0	Disable. LEDO is always On for each frame.						
LED0_Sub			1	Enable. LED0 is On and Off cycle in turn.			rn.			

10.6.3.2 LED1_Sub_EnH Register

Register Name	LED1_Sub_EnH							
Bank	0			Add	Address 0x4B			
Access	R/W			Reset	Value	0x01		
Bit	7 6 5 4 3 2 1						0	
Field	Reserved						LED1_Sub	
Description	Bit[0] is used	d to enable f	rame cycle (of Channel 1.				
Field	Access	Reset	Value		<u> </u>	Description		
LED1 Cub	Cub D/W 1			Disable. LED1 is always On for each frame.				
FEDT_200	LED1_Sub R/W		1	Enable. LED1 is On and Off cycle in turn.				

10.6.3.3 LED2_Sub_EnH Register

Register Name	LED2_Sub_E	inH						
Bank	0			Add	Address 0x4C			
Access	R/W			Reset	Reset Value 0x01			
Bit	7	6	5	4	3	2	1	0
Field	Reserved						LED2_Sub	
Description	Bit[0] is used	d to enable f	rame cycle o	of Channel 2.				
Field	Access	Reset	Value			Description		
LED3 Cub	D/M/ 1	1	0	Disable. LED2 is always On for each frame.				
LED2_Sub	R/W	1	1	Enable. LED2	2 is On and (Off cycle in tur	rn.	

10.6.4 LED Frame Cycle Swap

10.6.4.1 LED_OnOff_Swap Register

Register Name	LED_OnOff_	_Swap							
Bank	0			Add	lress	0x4D			
Access	R/W			Reset	Value	0x01			
Bit	7	6	5	4	3	2	1	0	
Field		Reserved LED_Swa							
Description			-	rame swappin st set this bit	_		ound subtrac	tion mode	
Field	Access Reset Value Description								
LED Swan	D ///	0	0	Disable. On frame first then Off frame.					
LED_Swap	R/W 0	U	1	Enable. Off frame first then On frame.					

10.6.5 LED DAC AE Controls

10.6.5.1 AE_LEDO_DAC Registers

Register Name	AE_LED0_D	AE_LED0_DAC_Min								
Bank	0			Address 0x85						
Access	R/W			Reset	: Value	0x01	0x01			
Bit	7	6	5	4	3	2	1	0		
Field	Reserved		AE_LED0_DAC_Min[6:0]							
Description	This is the m	his is the minimum bound of AE control for LEDO DAC.								

Register Name	AE_LED0_D	DAC_EnH							
Bank	0	0			Address 0x8E				
Access	R/W			Reset	Reset Value 0x01				
Bit	7	6	5	4	3	2	1	0	
Field		Reserved							
Description	Bit[0] is to e	enable AE co	ntrol for LED	0 DAC.					
Field	Access	Reset	Value			Description			
45 15D0 D4C	D () A (1	0	Disable					
AE_LEDO_DAC	R/W 1		1	Enable					

10.6.5.2 AE_LED1_DAC Registers

Register Name	AE_LED1_C	AE_LED1_DAC_Min								
Bank	0			Address 0xA7						
Access	R/W			Reset Value 0x01						
Bit	7	6	5	4	3	2	1	0		
Field	Reserved		AE_LED1_DAC_Min[6:0]							
Description	This is the m	ne minimum bound of AE control for LED1 DAC.								

Register Name	AE_LED1_D	E_LED1_DAC_EnH								
Bank	0			Add	lress	0xB0	0xB0			
Access	R/W			Reset	: Value	0x01	0x01			
Bit	7	6	5	4	3	2	1	0		
Field	Reserved							AE_LED1_ DAC		
Description	Bit[0] is to e	nable AE co	ntrol for LED	1 DAC.						
Field	Access	Reset	Value			Description				
AE	D/M		0	Disable						
AE_LED1_DAC	R/W	/W 1	1	Enable						

10.6.5.3 AE_LED2_DAC Registers

Register Name	AE_LED2_C	DAC_Min						
Bank	0		Add	Address 0xC9				
Access	R/W			Reset Value 0x01				
Bit	7	7 6 5			3	2	1	0
Field	Reserved	ved AE_LED2_DAC_Min[6:0]						
Description	This is the minimum bound of AE control for LED2 DAC.							

Register Name	AE_LED2_D	AE_LED2_DAC_EnH							
Bank	0			Add	lress	0xD2			
Access	R/W			Reset	Reset Value 0x01				
Bit	7	6	5	3	2	1	0		
Field		Reserved						AE_LED2_ DAC	
Description	Bit[0] is to e	enable AE co	ntrol for LED	2 DAC.					
Field	Access	Reset	Value			Description			
AE LED2 DAC	R/W	1	0 Disable						
AE_LEDZ_DAC	JAC N, VV I		1	Enable					

10.6.5.4 LED_DAC_Change_Flag_EnH Registers

Register Name	LED_DAC_C	Change_Flag	_EnH						
Bank	0			Add	Address 0xE6				
Access	R/W			Rese	t Value	0x00	0x00		
Bit	7	6	5	4	3	2	1	0	
Field			Reserved			LED2_DAC _CH_ Flag	LED1_DAC _CH_ Flag	_	
Description	The LED DAC Change Flag for the respective LED0, LED1 and LED2 channel is set via this register.								
Field	Access	Reset	Value		[Description			
LEDO DAC CH. Flag	R/W	0	0	Disable					
LEDO_DAC_CH_ Flag	K/ VV	U	1	Enable					
LED1 DAC CH Flag	R/W	0	0	Disable					
LEDI_DAC_CH_ Flag	N/ VV	O	1	Enable					
LED2_DAC_CH_ Flag	D /\//	1	0	Disable					
	R/W 1	1	Enable						

10.6.6 LED DAC Controls

10.6.6.1 LED_Man_EnH Registers

Register Name	LED0_Man	D0_Man_EnH									
Bank	1	1			Address		0xB4				
Access	R/W			Reset	Reset Value 0x00						
Bit	7	6	5	4	3	2	1	0			
Field	Reserved							LED0_Man			
Description	Bit[0] is to e	enable LED0	manual mod	e. This bit is a	ctive high.						
Field	Access	Reset	Value			Description					
LEDO Man	R/W	0	0	Disable							
LED0_Man	r/ vv	U	1	Enable							

Register Name	LED1_Man_	ED1_Man_EnH								
Bank	1			Add	Address 0xB5					
Access	R/W			R/W Reset Value 0x00						
Bit	7	6	5	4	3	2	1	0		
Field	Reserved							LED1_Man		
Description	Bit[0] is to e	enable LED1	manual mod	le. This bit is a	ctive high.					
Field	Access	Reset	Value			Description				
LED1 Man	D /\\/	D ////		Disable						
LED1_Man	R/W 0	1	Enable							

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Register Name	LED2_Man	_EnH							
Bank	1			Ado	dress	0xB6			
Access	R/W			Reset	: Value	e 0x00			
Bit	7	6	5	4	3	2	1		0
Field		Reserved L							LED2_Man
Description	Bit[0] is to e	enable LED2	manual mod	e. This bit is a	ctive high.				
Field	Access	Reset	Value			Description	\(\)		
LED2 Man	D /\A/	0	0	Disable					
LED2_Man	R/W 0	1	Enable						

10.6.6.2 LED_DAC_EnL Registers

Register Name	LED0_DAC_	EnL					_	
Bank	1			Add	dress	ress 0xB7		
Access	R/W			Rese	t Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field				Reserved				LED0_DAC
Description	Bit[0] is to e	nable AE co	ntrol for LED	00 DAC. This b	it is active l	ow.		
Field	Access	Reset	Value			Description		
1500 040	D /\\/	0	0	Enable				
LEDU_DAC	LEDO_DAC R/W	0	1	Disable				

Register Name	LED1_DAC_	EnL							
Bank	1			Add	ress	0xB8			
Access	R/W	R/W			: Value	0x00	0x00		
Bit	7	6	5	4	3	2	1	0	
Field				Reserved	ved LED1_D				
Description	Bit[0] is to e	enable AE co	ntrol for LED	1 DAC. This bi	t is active lo	DW.			
Field	Access	Reset	Value			Description			
LED1 DAC	R/W	0	0	Enable					
LED1_DAC	K/ VV	0	1	Disable					

Register Name	LED2_DAC_	LED2_DAC_EnL							
Bank	1			Add	ress	0xB9			
Access	R/W			Reset	Value	0x00			
Bit	7 6 5 4 3 2 1						1	0	
Field	Reserved							LED2_DAC	
Description	Bit[0] is to e	enable AE co	ntrol for LED	2 DAC. This bi	t is active lov	N.			
Field	Access	Reset	Value			Description			
LED3 DAC	15D2 DAC - D/M	0	0	Enable					
LED2_DAC	R/W	U	1	Disable			·		

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10.6.6.3 LED DAC Code Registers

Register Name	LED0_DAC_Code									
Bank	1			Add	Address OxBA					
Access	R/W			Reset	: Value	0x40				
Bit	7	6	5	4	3	2	1	0		
Field	Reserved	LED0_DAC_Code[6:0]								
	Bit[6:0] is us	ed to adjust	ed to adjust LED0 driving current.							
Description	Drive Currer	nt = 0.7mA x	LEDO_DAC_C	Code[6:0] valu	ie.					
Description	If AE_LEDO_DAC_EnH = 1 (bank0), LEDO_DAC_Code is at the maximum current for AE adjust.									
	If AE_LEDO_DAC_EnH = 0 (bank0), LEDO_DAC drive current is set according to LEDO_DAC_Code[6:0].									

Register Name	LED1_DAC_	LED1_DAC_Code									
Bank	1			Add	dress	OxBB					
Access	R/W			Reset	: Value	0x40	0x40 2 1 0				
Bit		6	6 5 4 3 2 1 0								
Field	Reserved		LED1_DAC_Code[6:0]								
		-	d to adjust LED1 driving current.								
Description			= 0.7mA x LED1_DAC_Code[6:0] value.								
	If AE_LED1_DAC_EnH = 1 (bank0), LED1_DAC_Code is at the maximum drive current for AE adjust. If AE_LED1_DAC_EnH = 0 (bank0), LED1_DAC drive current is set according to LED1_DAC_Code[6:0].										

Register Name	LED2_DAC_	_Code								
Bank	1			Ad	dress	0xBC				
Access	R/W			Rese	et Value	0x40	0x40			
Bit	7	6	5	4	3	2	1	0		
Field	Reserved		LED2_DAC_Code[6:0]							
	Bit[6:0] is us	ed to adjust	LED2 drivii	ng current.						
Description	Drive Currer	nt = 0.7mA x	t = 0.7mA x LED2_DAC_Code[6:0] value.							
Description	If AE_LED2_DAC_EnH = 1 (bank0), LED2_DAC_Code is at the maximum current for AE adjust.									
	If AE_LED2_DAC_EnH = 0 (bank0), LED0_DAC drive current is set according to LED2_DAC_Code[6:0].									

10.7 ADC Normalized Mode

10.7.1 Normalized_Mode_EnL Registers

Register Name	Normalized	Normalized_Mode_EnL_1							
Bank	0			Add	dress	0x50			
Access	R/W			Reset	t Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field				Reserved				Normalized	
Register Name	Normalized	Normalized_Mode_EnL_2							
Bank	0			Add	dress	0x51	0x51		
Access	R/W			Reset	t Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field				Reserved				Normalized	
Description	Bit[0] are us	ed to enable	e ADC norma	lized mode.					
Field	Access	Reset	Value			Description			
Normalizad	D /\A/	0	0	Enable					
Normalized	R/W	0	1	Disable					

10.7.2 Normalized_Right_Shift Register

Register Name	Normalize	Normalized_Right_Shift								
Bank	0			Ade	dress	0x56	0x56			
Access	R/W			Reset Value 0x07						
Bit	7	6	5	4	3	2	1	0		
Field		Reserved		Normalized_Right_Shift[4:0]						
Description	Bit[4:0] is u	Bit[4:0] is used to right shift ADC Normalized value when enable Normalized Mode.								

10.8 Touch Detection Controls

10.8.1 Touch_Detect_EnH Registers

Register Name	Touch_Dete	Touch_Detect_EnH							
Bank	0			Add	Address 0x5A				
Access	R/W			Reset	Value	0x00			
Bit	7 6 5 4 3 2 1						0		
Field	Reserved Touch							Touch_Det	
Description	Bit[0] is used	d to enable t	he Touch De	etection mode	2.			_	
Field	Access	Reset	Value			Description		_	
Touch Dot	D ///	0	0	Disable					
Touch_Det 	R/W	U	1	Enable					

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10.8.2 Touch Detection Upper Threshold Registers

Register Name	TouchDete	TouchDetection_Upper_TH_1								
Bank	0			Add	lress	0x5C				
Access	R/W			Reset	: Value	0x00				
Bit	7	6	5	4	3	2	2 1 0			
Field			Tou	uchDetection_	_Upper_TH	[7:0]				
Register Name	TouchDete	ction_Upper	_TH_2				* • 4			
Bank	0			Add	dress	0x5D				
Access	R/W			Reset	: Value	0x02	0x02			
Bit	7	6	5	4	3	2	1	0		
Field		TouchDetection_Upper_TH[15:8]								
Register Name	TouchDete	TouchDetection_Upper_TH_3								
Bank	0			Add	dress	0x5E				
Access	R/W			Reset	: Value	0x00				
Bit	7	6	5	4	3	2	1	0		
Field			Touc	chDetection_l	Upper_TH[2	23:16]				
Register Name	TouchDete	ction_Upper	_TH_4	X						
Bank	0			Add	dress	0x5F				
Access	R/W			Reset	: Value	0x00				
Bit	7	6	5	4	3	2	1	0		
Field			Touc	chDetection_l	Upper_TH[3	31:24]				
Description	These are the Refer to Figure	_	o set the tou	ch detection (upper thres	hold. The thres	shold width i	s 32-bits.		

10.8.3 Touch Detection Lower Threshold Registers

Register Name	TouchDete	ction_Lower	_TH_1						
Bank	0			Add	dress	0x60			
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field			Tou	uchDetection _.	_Lower_TH[7:0]			
Register Name	TouchDete	ction_Lower	_TH_2				* • •		
Bank	0			Ado	dress	0x61			
Access	R/W			Reset	: Value	0x02			
Bit	7	6	5	4	3	2	1	0	
Field		TouchDetection_Lower_TH[15:8]							
Register Name	TouchDete	FouchDetection_Lower_TH_3							
Bank	0			Ado	dress	0x62			
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field			Touc	hDetection_	Lower_TH[2	3:16]			
Register Name	TouchDete	ction_Lower	_TH_4	X					
Bank	0			Add	dress	0x63			
Access	R/W			Reset	: Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field			Touc	hDetection_	Lower_TH[3	1:24]			
Description	These are th Refer to Figu	_	o set the tou	ch detection I	Lower thresl	nold. The thre	shold width i	s 32-bits.	

10.8.4 Touch Detection Count Registers

10.8.4.1 Touch Detection Count Threshold Register

Register Name	TouchDete	TouchDetection_Count_TH									
Bank	0			Add	dress	0x64					
Access	R/W			Reset	: Value	0x0A	0x0A				
Bit	7	6	5	4	3	2	2 1 0				
Field		Reserved		TouchDetection_Count_TH[4:0]							
	This register	is the Touch	Count Thres	shold in Toucl	n Detection. (Count value is	s from 0 to 30).			
Description	Touch flag a	ouch flag and INT pin will be asserted when counting number > TouchDetection_Count_TH.									
	Counting period is one data report interval.										

10.8.4.2 No Touch Detection Count Threshold Register

Register Name	NoTouchDe	etection_Cou	int_TH							
Bank	0	0			dress	0x65	0x65			
Access	R/W			Reset	: Value	0x0A	0x0A			
Bit	7	6	5	4	3	2	2 1 0			
Field		Reserved			NoTouch	Detection_Cou	ection_Count_TH[4:0]			
	This register	is the No-to	uch Count Th	nreshold in To	ouch Detect	ion. Count val	ue is from 0	to 30.		
Description	Touch flag w	vill be de-asse	Detection_Co	etection_Count_TH. Counting period						
	is one data r	eport interva	ıl.							

10.8.5 Touch Detection Interrupt Register

Register Name	INT_Touchl	Det_Mask					· ·		
Bank	2			Addı	Address		0x76		
Access	R/W			Reset '	Reset Value 0x00				
Bit	7	6	5	4	3	2	1	0	
Field		Reserved						TouchDet_ Mask	
Description	Bit [0] is to	mask touch (detection int	errupt.					
Field	Access	Reset	Value			Description			
Taylob Dat Maak	D /\A/	0	0	Unmask					
TouchDet_Mask	R/W	0	1	Mask					

Register Name	INT_Touchl	Det_Clear							
Bank	2			Add	Address 0x77				
Access	R/W			Reset	Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field		Reserved						TouchDet_ Clear	
Description	1. Set Bit[C		of TouchDet _.	_Clear bit will	clear the to	ouch detectior	n interrupt.		
Field	Access	Reset	Value			Description			
TouchDet Clear	D /\\/	0	0	Low					
	R/W 0		1	High	·		·		

10.9 Clock/Timer Controls

10.9.1 Low Power Timer Register

Register Name	LPT_EnH						
Bank	1			Add	Address		
Access	R/W			Reset	Value	0x01	
Bit	7	6	5	4	3	2	1 0
Field				Reserved			LPT
Description	Bit[0] is to en	nable the 32	kHz low pow	er timer.			
Field	Access	Reset	Value			Description	
LDT	R/W	1	0	Disable			
LPT	r/VV	Τ,	1	Enable			

10.9.2 Oscillator Register

Register Name	OSC_EnL							
Bank	1			Add	Address 0xC3			
Access	R/W			Reset	t Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field		Reserved						OSC
Description	Bit[0] is to e	nable the 32	MHz interna	l oscillator.				
Field	Access	Reset	Value			Description		
OSC	D /\\/	0		Enable				
USC	R/W	0	1	Disable				

10.10 Timing Generator Controls

10.10.1 TIMER_Gen_Enable Register

Register Name	TIMER_Ger	_Enable							
Bank	1			Add	Address		0xD5		
Access	R/W			Reset Value 0x00					
Bit	7	6	5	4	3	2	1	0	
Field				Reserved			*	TIMER_Gen	
Description	Bit[0] is to e	nable the tim	ning generat	or in the senso	or.				
Field	Access	Reset	Value			Description			
TIMED Con	D /\A/	D // A/		Disable					
TIMER_Gen	R/W 0		1	Enable					

10.10.2 TIMER_Gen_Period Registers

TIMER_Ger	_Period_LB		. 🌢					
1			Add	dress	0xD6			
R/W			Reset	: Value	0x40	0x40		
7	6	5	4	3	2	1	0	
			TIMER_Gen_	Period[7:0]				
TIMER_Ger	ER_Gen_Period_HB							
1				Address 0xD7				
R/W			Reset	: Value	0x01			
7	6	5	4	3	2	1	0	
			TIMER_Gen_	Period[15:8]				
TIMER_Gen	_Period[15:0] is 16-bit w	idth used to r	eport the pe	riod of timing	g generator.		
1-bit step is	31.25μs. Per	iod = TIMER_	_Gen_Period[[15:0] x 31.25	5 μs			
Default setting = 0x140 = 320								
Default Period = 320 x 31.25 μs = 10000 μs = 10ms								
Thus, Default Report Rate = 1/10ms = 100Hz								
	1 R/W 7 TIMER_Ger 1 R/W 7 TIMER_Gen 1-bit step is Default setti Default Perio	1 R/W 7 6 TIMER_Gen_Period_HE 1 R/W 7 6 TIMER_Gen_Period[15:0 1-bit step is 31.25µs. Per Default setting = 0x140 = Default Period = 320 x 33	R/W 7 6 5 TIMER_Gen_Period_HB 1 R/W 7 6 5 TIMER_Gen_Period[15:0] is 16-bit w 1-bit step is 31.25μs. Period = TIMER_Default setting = 0x140 = 320 Default Period = 320 x 31.25 μs = 100	1 R/W Reset 7 6 5 4 TIMER_Gen_ TIMER_Gen_Period_HB 1 Add R/W Reset 7 6 5 4 TIMER_Gen_ TIMER_Gen_ TIMER_Gen_ TIMER_Gen_ TIMER_Gen_Period[15:0] is 16-bit width used to r 1-bit step is 31.25μs. Period = TIMER_Gen_Period[Default setting = 0x140 = 320 Default Period = 320 x 31.25 μs = 10000 μs = 10ms	1	1	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	

10.11 FIFO Buffer Registers

10.11.1 Set FIFO Report Number Register

Register Name	SetFIFO_Rp	tNum								
Bank	1	1			ress	OxEA				
Access	R/W			Reset	: Value	0x03				
Bit	7	6	5	4	3	2	1 0			
Field				SetFIFO_Rp	tNum[7:0]		* 1/7			
	SetFIFO_Rpt	Num[7:0] set	ts the Numb	er of FIFO ent	try valid for o	data ready rep	oort interrupt.			
Description	SetFIFO_Rpt	tFIFO_RptNum[7:0] = report number +1								
	Default value	e is 0x03 and	report num	ber is 2.						

10.11.2 FIFO Checksum Registers

Register Name	Readout_FI	FO_Checks	um_1			VI			
Bank	2			Add	dress	0x80			
Access	Read Only			Rese	t Value	0x00	0x00		
Bit	7	6	5	4 3 2 1				0	
Field				FIFO_Chec	ksum [7:0]				
Register Name	Readout_FI	FO_Checks	ım_2						
Bank	2			Add	dress	0x81			
Access	Read Only	<u> </u>			t Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field		FIFO_Checksum [15:8]							
Register Name	Readout_FI	eadout_FIFO_Checksum_3							
Bank	2			Add	dress	0x82			
Access	Read Only			Reset Value 0x00					
Bit	7	6	5	4	3	2	1	0	
Field			,	FIFO_Check	sum [23:16]	•			
Register Name	Readout_FI	FO_Checks	ım_4						
Bank	2			Add	dress	0x83			
Access	Read Only			Rese	t Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field		FIFO_Checksum [31:24]							
Description	Checksum [3 data for Hos			data_read_c	out. Chip har	dware will aut	tomatic sum	all burst	

10.11.3 FIFO Interrupts Registers

10.11.3.1 INT_SramFIFO_DR Registers

Register Name	INT_SramFl	IFO_DR_Mas	sk						
Bank	2			Add	lress	0x74	0x74		
Access	R/W			Reset	Value	0x00			
Bit	7	6	5	4	3	2	1	0	
Field			Reserved DR_Ma						
Description	Bit [0] is to	mask the dat	a ready inte	rrupt of SDRA	M FIFO buff	er			
Field	Access	Reset	Value			Description			
DD Mask	D /\A/	0	0	Unmask					
DR_Mask	R/W	U	1	Mask					

Register Name	INT_SramF	T_SramFIFO_DR_Clear									
Bank	2			Addı	Address		0x75				
Access	R/W			Reset	Reset Value 0x00						
Bit	7 6 5 4 3 2 1						0				
Field		Reserved DR_Cle						DR_Clear			
Description	1. Set Bit[C	A High to Low transition of DR_Clear bit will clear the data ready interrupt of SDRAM FIFO buffer. Set Bit[0] to 1 Then set Bit[0] to 0									
Field	Access	Reset	Value			Description					
DR Clear	R/W	0	0	Low							
DN_Clear	ry VV	U	1	High							

10.11.3.2 INT_SramFIFO_Overflow Registers

Register Name	INT_SramF	IFO_Overflo	w_Clear					
Bank	2			Add	lress	0x8C		_
Access	R/W				Reset Value 0x00			
Bit	7	6	5	4	3	2	1	0
Field		Reserved OVF_CI						
	A High to Lo	A High to Low transition of OVF_Clear bit will clear the FIFO Overflow interrupt.						
Description	1. Set Bit[C)] to 1						
	2. Then set	t Bit[0] to 0						
Field	Access	Reset	Value			Description		
OVF Clear	R/W	0	0	Low				
OVF_Clear	ry VV	U	1	High				

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Register Name	INT_SramFl	FO_Overflo	w_Mask					
Bank	2	2 Address 0x8D						
Access	R/W			Reset	: Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field				Reserved				OVF_Mask
Description	Bit [0] is to n	nask the FIF0	Overflow i	nterrupt.				
Field	Access	Reset	Value			Description	\	
OVE Mask	OVE Mosk			Unmask				
OVF_Mask	R/W	0	1	Mask				

10.11.3.3 INT SdramFIFO Underflow Registers

Register Name	INT_SramF	IFO_Underfl	ow_Clear					
Bank	2			Addı	ress	0x8E		
Access	R/W			Reset '	Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field				Reserved				UDF_Clear
	A High to Lo	w transition	of UDF_Clear	r bit will clear t	the FIFO U	nderflow interr	upt.	·
Description	1. Set Bit[0)] to 1						
	2. Then set	t Bit[0] to 0						
Field	Access	Reset	Value			Description		
OVE Claar	R/W	0	0	Low				
OVF_Clear	r/VV	0	1	High	•		•	

Register Name	INT_SramF	IFO_Underfl	ow_Mask					
Bank	2			Ado	ress	0x8F		
Access	R/W			Reset	: Value	0x00		
Bit	7 6 5 4 3 2 1						0	
Field				Reserved				UNF_Mask
Description	Bit [0] is to r	mask the FIFO	O Underflow	interrupt.				
Field	Access	Reset	Value			Description		
LINE Mask	D ()A/	0	0	Unmask				
UNF_Mask	R/W	U	1	Mask				

10.12 Interrupt Controls

10.12.1 Interrupt Setting

10.12.1.1 Interrupt Mode Selection Register

Register Name	INT_Model	_Sel					
Bank	2			Ado	lress	0x25	
Access	R/W			Reset	: Value	0x00	
Bit	7	6	5	4	3	2	1 0
Field			Reserved			IN	T_Mode_Sel [2:0]
Description	Interrupt Mo	ode Selectior	า				
Field	Access	Reset	Value			Description	1
			010	INT Register	Array		
INT_Mode_Sel	R/W	000	100	Touch Flag r	eadout		
			Others	Reserved			

10.12.1.2 Interrupt Direction Register

Register Name	INT_Output_EnL							
Bank	2			Add	Address 0x29			
Access	R/W			Reset	Value	0x01		
Bit	7 6 5 4 3 2 1						0	
Field				Reserved				INT_Out
Description	Interrupt Ou	ıtput Directio	on					
Field	Access	Reset	Value			Description		
INT Output	D /\A/	R/W 0 Output						
INT_Output	R/W	U	1	Input				

10.12.1.3 Interrupt Mask All Register

Register Name	All_INT_Ma	isk						
Bank	2			Add	ress	0x78		
Access	R/W			Reset	Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field				Reserved				All_Mask
Description	Bit [0] is to n	nask all the i	nterrupts.					
Field	Access	Reset	Value			Description		
All Mask	R/W	0	0	Unmask				
All_Mask	ry vv	0	1	Mask				

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10.12.1.4 Interrupt Type Register

Register Name	INT_Type								
Bank	2			Add	dress 0x7A				
Access	R/W			Reset	Value	0x01	0x01		
Bit	7	6	5	4 3 2 1				0	
Field		Reserved INT_						INT_Type	
Description	Bit [0] is to s	elect the typ	es of interru	pt for triggeri	ng.		> , (,)		
Field	Access	Reset	Value			Description			
INIT Tuno	D /\\/	1	0	Level Sensitive					
INT_Type	R/W	1	1	Edge (Pulse)	Sensitive				

10.12.1.5 Interrupt Pulse Width Register

Register Name	INT_Pulse_	INT_Pulse_Width								
Bank	2			Add	ress	0x7B				
Access	R/W			Reset	Value	0x08				
Bit	7	6	5	4	3	2	1	0		
Field				INT_Pulse_\	Width [7:0]					
	INT_Pulse_V	/idth [7:0] se	ets the width	of edge/pulse	e of an interr	upt as trigge	ering signal.			
Description	Pulse Width	= INT_Pulse_	_Width [7:0]	x62.5ns						
	Default = 8 x	62.5ns = 50	00ns = 0.5μs							

10.12.2 Interrupt Mode Status

10.12.2.1 Touch Flag Register

Register Name	Touch_Flag	_readout						
Bank	2			Add	ress	0x45		
Access	Read only			Reset	Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field				Reserved				Touch
Description	Bit [0] repor	ts the readou	ut of touch fl	ag status				
Field	Access	Reset	Value			Description		
Touch	R/W	0	0	No Touch				
Touch	n/ VV	U	1	Touch				

10.12.2.2 Interrupt Status Array Register

Register Name	INT_Reg_A	rray							
Bank	2			Add	lress	0x73	0x73		
Access	Read only			Reset Value 0x00					
Bit	7	6	5	4	3	2	1	0	
Field		Rese	erved		FIFO_UND	FIFO_OVF	Touch_Det	FIFO_DR	
Description	Bit[3:0] rep	ort the Interi	rupt Status A	rray status			\(\)		
Field	Access	Reset	Value			Description			
FIFO_UND	R	0	Х	INT_SramFIF	O_Underflov	v			
FIFO_OVF	R	0	Х	INT_SramFIF	O_Overflow				
Touch_Det	R	0	Х	INT_Touch_Detection					
FIFO_DR	R	0	Х	INT_SramFIF	O_Data_Rea	dy			

10.13 Read AE Information

10.13.1 Exposure Time Registers

Register Name	CH0_Exposu	ure_Time_L	В	<u> </u>							
Bank	2			Ad	dress	0xA0					
Access	Read Only			Rese	t Value	0x00	0x00				
Bit	7	6	5	4	4 3 2 1			0			
Field		CH0_Expusure_Time[7:0]									
Register Name	CH0_Exposi	CH0_Exposure_Time_HB									
Bank	2										
Access	Read Only			Rese	t Value	0x00					
Bit	7	6	5	4	3	2	1	0			
Field			(CH0_Expusur	CHO_Expusure_Time [15:8]						
	Read exposure time of Channel 0. CH0_Expusure_Time [7:0] are the lower 8bits and CH0_Expusure_Time [15:8] are the upper 8bits.										
Description						are the lower 8	Bbits and				
Description						re the lower 8	Bbits and				
Description Register Name		re_Time [15	:8] are the u			re the lower 8	Bbits and				
·	CH0_Expusu	re_Time [15	:8] are the u	pper 8bits.		oxA2	Bbits and				
Register Name	CH0_Expusu CH1_Exposu	re_Time [15	:8] are the u	pper 8bits.	Time [7:0] a		Bbits and				
Register Name Bank	CH1_Exposu	re_Time [15	:8] are the u	pper 8bits.	Time [7:0] a	0xA2	Bbits and	0			
Register Name Bank Access	CH1_Exposu	re_Time [15 ure_Time_L	:8] are the u	pper 8bits. Ad Rese	dress t Value 3	0xA2 0x00 2		0			
Register Name Bank Access Bit	CH1_Exposu	re_Time [15 ure_Time_L	:8] are the u	Ad Rese	dress t Value 3	0xA2 0x00 2		0			
Register Name Bank Access Bit Field	CH1_Exposu 2 Read Only 7	re_Time [15 ure_Time_L	:8] are the u	Ad Rese 4 CH1_Expusu	dress t Value 3	0xA2 0x00 2		0			

4

Read exposure time of Channel 1. CH1_Expusure_Time [7:0] are the lower 8bits and

CH1_Expusure_Time [15:8]

3

2

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Bit

Field

Description

SEE. FEEL. TOUCH.

7

6

0

CH1_Expusure_Time [15:8] are the upper 8bits.

5

Register Name	CH2_Exposi	ure_Time_LE	3					
Bank	2			Add	lress	0xA4		
Access	Read Only			Reset	Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field				CH2_Expusur	re_Time[7:0]			
Register Name	CH2_Exposi	H2_Exposure_Time_HB						
Bank	2			Add	lress	0xA5		
Access	Read Only			Reset	Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field			(CH2_Expusure	e_Time [15:8]			
Description	Read exposu CH2_Expusu			2_Expusure_ oper 8bits.	Гіте [7:0] are	the lower 8	bits and	

10.13.2 LED DAC

Register Name	LED0_DAC_\	/alue						
Bank	2				Address 0xA6			
Access	Read Only			Reset '	Value	0x00		
Bit	7	6	5	4	3	2	1	0
Field	Reserved			LED0_	DAC_Valu	ie[6:0]		
Description	Read DAC val	ue of LED Cl	hannel 0.					

Register Name	LED1_DAC_Value							
Bank	2			Address		0xA7		
Access	Read Only			Reset Value		0x00		
Bit	7	6	5	4	3	2	1	0
Field	Reserved	LED1_DAC_Value[6:0]						
Description	Read DAC value of LED Channel 1.							

Register Name	LED2_DAC_Value							
Bank	2			Address		0xA8		
Access	Read Only			Reset Value		0x00		
Bit	7	6	5	4	3	2	1	0
Field	Reserved	LED2_DAC_Value[6:0]						
Description	Read DAC va	DAC value of LED Channel 2.						

11.0 Appendix

11.1 Touch Setting of 3.8Hz for INT Application

11.1	Touch Setting of 3.8Hz
7f	01 //switch to bank1
E6	C8
E7	00
F1	00
07	01
ΑE	06
AF	07
ВА	7C
6C	10
6D	10
7A	01
6F	10
7F	00 //switch to bank0
80	FF
09	03
5A	01
5C	58
5D	02
60	00
61	02
64	01
65	01
35	80
36	02
8C	00
8E	00
DE D9	00 01
DD	04
3B	01
43	00
47	01
48	00
49	00
4A	01
4D	01
16	01
13	01
14	01
15	01
50	01
51	01

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00

59

```
57
       00
6B
       00
6C
       00
3E
       00
0D
       78
0E
       00
7F
       02 //switch to bank2
25
       02
29
       00
2d
       01
       0C
4F
66
       01
67
       01
       01
68
69
       01
6A
       01
//6B
       01
//6C
       01
6D
       01
6E
       01
6F
       01
70
       01
74
       01
76
       00
       01
7A
       FF
7B
8D
       01
8F
       01
92
       00
7F
       01 //switch to bank1
Α2
       40
7C
       01
4C
       01
4F
       07
3F
       04
0C
       05
       05
4D
52
       05
86
       50
92
       1C
98
       1D
9A
       42
81
       01
3B
       00
       C9
EΑ
Α4
       50
```

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A5	00
A6	52
Α7	00
Α8	53
A9	00
D6	FF
D7	1F
D8	01
D9	00
DA	10
DB	00
DC	16
DD	00
DE	17
DF	00
E0	FE
E1	1F

11.2 Touch Setting of 3.8Hz for Touch Flag Application

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```
57
       00
6B
       00
6C
       00
3E
       00
0D
       78
0E
       00
7F
       02 //switch to bank2
25
       04
29
       00
2d
       01
4F
       0C
66
       01
67
       01
       01
68
69
       01
6A
       01
//6B
       01
//6C
       01
6D
       01
6E
       01
6F
       01
70
       01
74
       01
76
       01
8D
       01
8F
       01
92
       00
7F
       01 //switch to bank1
A2
       40
7C
       01
4F
       07
3F
       04
       05
0C
4D
       05
52
       05
86
       50
92
       1C
98
       1D
9A
       42
81
       01
3B
       00
EΑ
       C9
Α4
       50
A5
       00
       52
A6
Α7
       00
```

Low Power Optical Heart Rate Detection Sensor

Α8	53
A9	00
D6	FF
D7	1F
D8	01
D9	00
DA	10
DB	00
DC	16
DD	00
DE	17
DF	00
EO	FE
E1	1F

11.3 PPG Setting of 20Hz 7f 01 //switch to bank1 E6 **C8** E7 00 07 01 ΑE 06 AF 07 00 4D 7C ВА ВВ 7C 7C BC 06 BDBE 06 BF 06 06 В1 06 В2 В3 06 6A 00 6B 01 6C 10 6D 10 7A 00 6F 10 7F 00 //switch to bank0 80 FF 09 03 4F 0C 07 E6 8C 00 ΑE 01 01 D0 8E 00 D2 01 ВО 01 27 80 28 12 35 C0 36 12 37 C0 38 12 39 CO 3A 12 DE 00 D9 01 DD 04

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01

3B

3C	15
3D	15
47	01
48	01
49	01
4A	01
4B	00
4C	00
4D	00
16	00
13	01
14	01
15	01
50	00
59	00
56	00
57	00
6B	01
6C	00
8F	01
B1	01
3E	02
3F	04
40	04
0D	78
OE	00
0F	FO
10	00
11	FO
12	00
6D	F0
6E	00
6F	00
70	02
71	10
72	00
77	00
78	OC
79	00
7A	08
7B	00
7C	ОВ
7D	00
7E	09
80	00
81	0D
OΤ	UD

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SEE. FEEL. TOUCH.

82 83 85 90 91 92 93	00 07 01 F0 00 20 12
94	10
95	00
9A	00
9B	OC
9C	00
9D 9E	08 00
9F	OB
A0	00
A1	09
A2	00
A3	OD
A4	00
A5	07
A7 B2	01 F0
B3	00
B4	20
B5	12
B6	10
В7	00
ВС	00
BD	0C
BE BF	00 08
CO	00
C1	OB
C2	00
C3	09
C4	00
C5	OD
C6	00
C7	07
C9 7F	01 02 //switch to bank2
25	02 //switch to bank2
29	00
2d	01
4F	10

66	01
67	01
68	01
69	01
6A	01
//6B	01
//6C	01
6D	01
6E	01
70	01
7B	FF
7F	01 //switch to bank1
A2	40
7C	01
4F	07
3F	04
OC	05
4D	05
52	05
86	50
92	1C
98	1D
9A	42
81	01
3B	00
EA	C9
A4	50
A5	00
A6	52
A7	00
A8	53
A9	00
D6	40
D7	06
D8	01
D9	00
DA	11
DB	00
DC	84
DD	02
DE	85
DF	02
EO	3F
E1	06

11.4 PPG Setting of 20Hz Long Exposure Time

01 //switch to bank1 7f E6 **C8** E7 00 07 01 ΑE 06 ΑF 07 00 4D 7C ВА ВВ 7C 7C BC 06 BDBE 06 BF 06 06 В1 06 В2 В3 06 6A 00 6B 01 6C 10 6D 10 7A 00 6F 10 7F 00 //switch to bank0 80 FF 09 03 4F 0C 07 E6 8C 00 ΑE 01 01 D0 8E 00 D2 01 BO 01 27 40 28 25 35 80 36 25 37 80 25 38 39 80 25 3A DE 00 D9 01

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04

01

DD

3B

3C	0A	
3D	0A	
47	01	
48	01	
49	01	
4A	01	
4B	00	
4C	00	
4D	00	
16	00	
13	01	
14	01	
15	01	
50 59	00 00	
56	00	
57	00	
6B	01	
6C	00	
8F	01	
В1	01	
3E	02	
3F	02	
40	02	
0D	78	
0E	00	
0F	C0	
10	12	
11	C0	
12 6D	12	
6D 6E	F0 00	
6F	00	
70	02	
	10	
71 72 77	00	
77	00	
78	00	
79	00	
7A	08	
7B	00	
7C	OB	
7D	00	
7E	09	
80	00	

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0D

81

82	00
83	07
85	01
90	FO FO
91	00
92	
	00
93	25
94	10
95	00
9A	00
9B	OC .
9C	00
9D	08
9E	00
9F	OB
A0	00
A1	09
A2	00
A3	OD
A4	00
A5	07
Α7	01
B2	FO
В3	00
B4	00
B5	25
B6	10
В7	00
ВС	00
BD	OC
BE	00
BF	08
C0	00
C1	OB
C2	00
C3	09
C4	00
C5	OD OD
C6	00
C7	07
C9	01
7F	02 //switch to bank2
7F 25	
	02
29 2-l	00
2d	01
4F	10

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66	01
67	01
68	01
69 6A	01 01
//6B	01
//6C	01
6D	01
6E	01
70	01
7B	FF
7F	01 //switch to bank1
A2	40
7C	01
4F	07
3F OC	04 05
4D	05
52	05
86	50
92	1C
98	1D
9A	42
81	01
3B	00
EA A4	C9 50
A4 A5	00
A6	52
A7	00
A8	53
A9	00
D6	40
D7	06
D8	01
D9 DA	00 11
DB	00
DC	C4
DD	02
DE	C5
DF	02
EO	3F
E1	06

11.5 PPG Setting of 200Hz 7f

01//switch to bank1

E6 **C8** E7 00

07 01

ΑE 06

AF 07

00 4D

7C ВА

ВВ 7C

7C BC

06 BD

BE 06

BF 06

06 В1 06 В2

В3 06

6A 00

6B 01

6C 10

6D 10

7A 00

80 6F

7F 00//switch to bank0

80 FF

09 03

4F 0C

07 E6

8C 00

ΑE 01

01 D0

8E 00

D2 01

ВО 01

60

27

28 OF

35 A0

36 0F 37 Α0

OF 38

39 A0

OF 3A

DE 00

D9 01

DD 04

3B 01

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SEE. FEEL. TOUCH.

3C	02
3D	02
43 44	00
45	00
45 47	01
48	01
49	01
4A	01
4B	00
4C	00
4D	00
16	00
13	01
14	01
15	01
50	00
59	00
56	00
57	00
6B	01
6C	00
8F	01
B1	01
3E	00
3F	00
40	00
0D	78
OE	00
0F	FO
10	00
11	FO
12	00
6D	F0
6E 6F	00 00
70	02
70	10
72	00
77	00
78	0C
79	00
7A	08
7B	00
7C	OB
7D	00

7E	09
80	00
81	OD
82	00
83	07
85	01
90	FO
91	00
92	40
93	OF
94	10
95	00
9A	00
9B	OC .
9C	00
9D	08
9E	00
9F	OB
A0	00
A1	09
A2	00
A3	OD
A4	00
A5	07
A7	01
B2	F0
B3	00
B4 B5	40 OF
B6	10
B7	00
BC	00
BD	0C
BE	00
BF	08
CO	00
C1	OB
C2	00
C3	09
C4	00
C5	OD
C6	00
C7	07
C9	01
7F	02//switch to bank2
25	02

29	9	00	
20		01	
41		0C	
66		01	
6		01	
68		01	
69		01	
6/		01	
61		01	
61		01	
70		01	
71		FF	
71			witch to bank1
22		50	
48		50	
A.		40	
70		01	
41		07	
31		04	
00		05	
41		05	
52		05	
86		50	
92		1C	
98		1D	
9/		42	
8		01	
31		00	
E		C9	
A		50	
A.		00	
А		52	
Α		00	
A		53	
A		00	
D		Α0	
D		00	
D		01	
D:		00	
D.		2C	
D		00	
D		8B	
D		00	
D		8C	
D		00	
E		9F	
E:		00	

11.6 Sleep Setting 7f 01 //switch to bank1 В4 В7 E6 **C8** E7 F1 ΑE ΑF ВА 7C 6C 6D 7A 6F 00 //switch to bank0 7F FF D6 5C 5D 8C 8E DE D9 DD 3B 4A 4D

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59	00
57	00
6B	00
6C	00
3E	00
43	00
0D	78
OE	00
7F	02 //switch to bank2
17	00
18	00
1F	00
29	00
2D	01
2B	00
2C	00
31	00
4F	10
66	01
67	01
68	01
69	01
6A	01
6B	01
6C	01
6D	01
6E	01
6F	01
70 74	01
74 76	00 01
78	01
78 7A	01
7B	FF F
8D	01
8F	01
92	00
7F	01 //switch to bank1
A2	40
7C	01
4C	01
4F	07
3F	04
0C	05
4D	05
52	05

86	50
92	1C
98	1D
9A	42
81	01
3B	00
EΑ	C9
A4	50
A5	00
A6	52
Α7	00
Α8	53
A9	00
D6	FF
D7	1F
D8	01
D9	00
DA	10
DB	00
DC	13
DD	00
DE	14
DF	00
E0	FE
E1	1F

Document Revision History

Revision Number	Date	Description
1.2	13 Mar 2015	1 st Creation, Preliminary version
1.4	21 May 2015	 Updated parameters in Section 2.0 Operating Specifications Added Section 1.5 ADC Normalized Mode Added Section 1.6 Power Saving Mechanism Added Section 3.2 Package Marking Added Section 5.0 Power States & Sequence Updated Section 8.1 Auto Exposure Control (AEC) Updated registers in Section 10.0 Registers Added code settings in Section 11.0 Appendix
1.5	12 Jun 2015	 Update Figure 10 Power-up and Power-off Sequence Timing Diagram Modify power up time from V_{DD} Modify SetFIFO_RptNum register description Modify sleep setting Added PPG setting of 200Hz
1.6	01 Jul 2015	 Update Sleep setting, Touch setting and PPG setting Update Package Marking Update PCB Layout Design Added Recommend Guideline for PCB Assembly Added Package Information Update Auto Exposure Control Diagram
1.7	15 Jul 2015	1. Update PPG setting of 20Hz and 200Hz
1.8	27 Aug 2015	 Update PPG setting of 20Hz and 200Hz and Touch Setting and Sleep Setting Modify IR Touch Detection current Modify VBGP Capacitor value to 0.1μF Modify Power Up From V_{DD} Time
1.9	02 Sep 2015	1. Modify Power Up From V _{DD} Time
2.0	15 Sep 2015	 Update Figure 12. Carrier Tape Drawing Add Section 11.4 PPG setting of 20Hz Long Exposure Time Setting Modify the setting value of LEDO DAC (Bank1 0xBA) to 7C in the Appendix
2.1	08 Oct 2015	 Update Table 1. Signal Pins Description Mask bank2 0x6B and 0x6C of Touch Setting and PPG Setting of 20Hz
2.2	03 Dec 2015	 Update HW Reset Time t_{reset} Update Figure 31. Power-up and Power-off Sequence Timing Diagram